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Global photonics markets and trends over the next decade

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Agenda

- ❑ Key trends
- ❑ Target Markets: large & facing a growing gap
 - ❑ Market environment
 - ❑ Market gap
- ❑ Market technology opportunities
 - ❑ Faster devices, lower power, lower cost, robustness
- ❑ Roadmap update
 - ❑ What we predicted from 2016
 - ❑ What is happening in 2019
- ❑ Summary

NB: These green bars give a summary of each slide

What does it take...

...to enable today's data services such as streaming video, social media, activity trackers, e-commerce?



...to enable tomorrow's data services (more intelligent, more immediate, richer)?

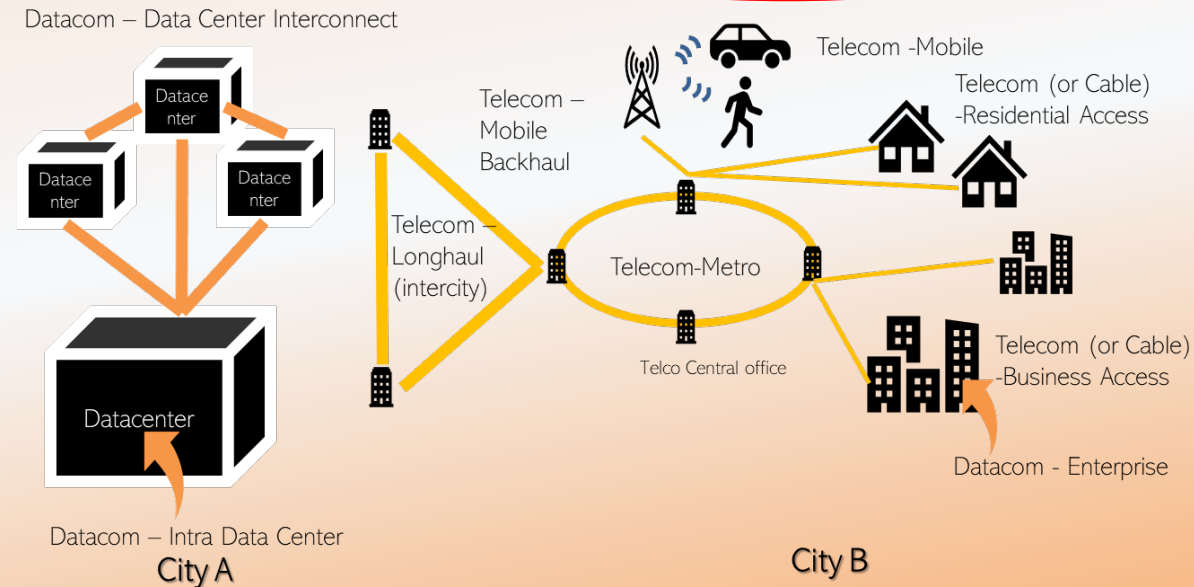


Future products will be driven and enabled by photonics

Actually...all this!

Massive datacenters and high-speed fiber optics enable today's data services such as streaming video, social media, activity trackers, e-commerce

Experts agree it will take radical innovation to enable tomorrow's data services (more intelligent, more immediate, richer)



Radical innovation needed...

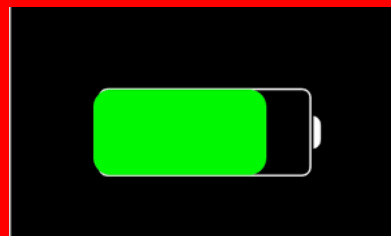
Delivering radical innovation...

Photonics must deliver solutions:

Faster devices
(100GHz+)



Lower Power
(Low voltage)



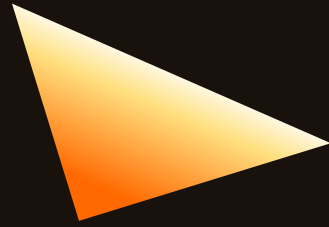
Lower cost
(Easy fab)



Robust
(Stable)



To enable faster, lower power, lower cost internet...

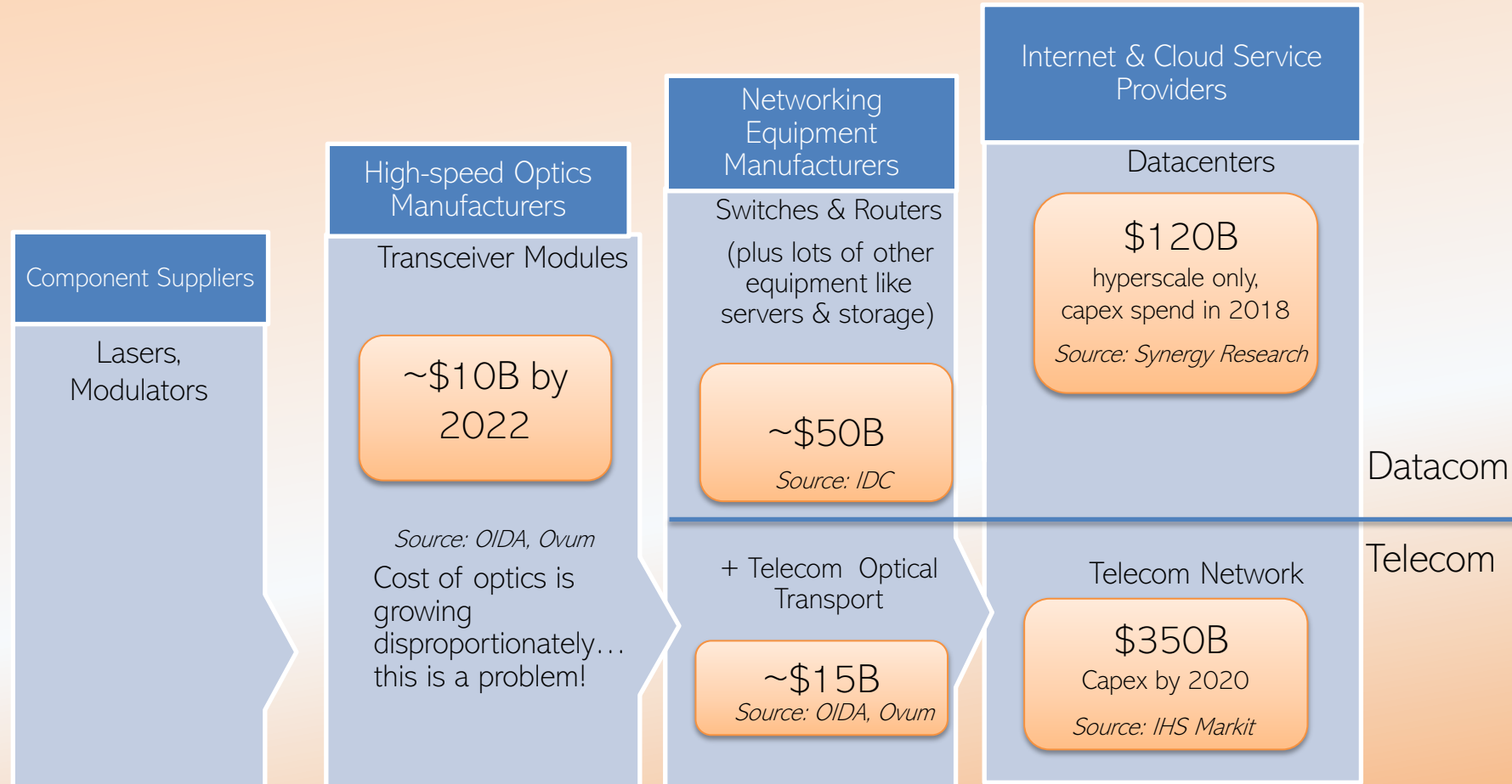


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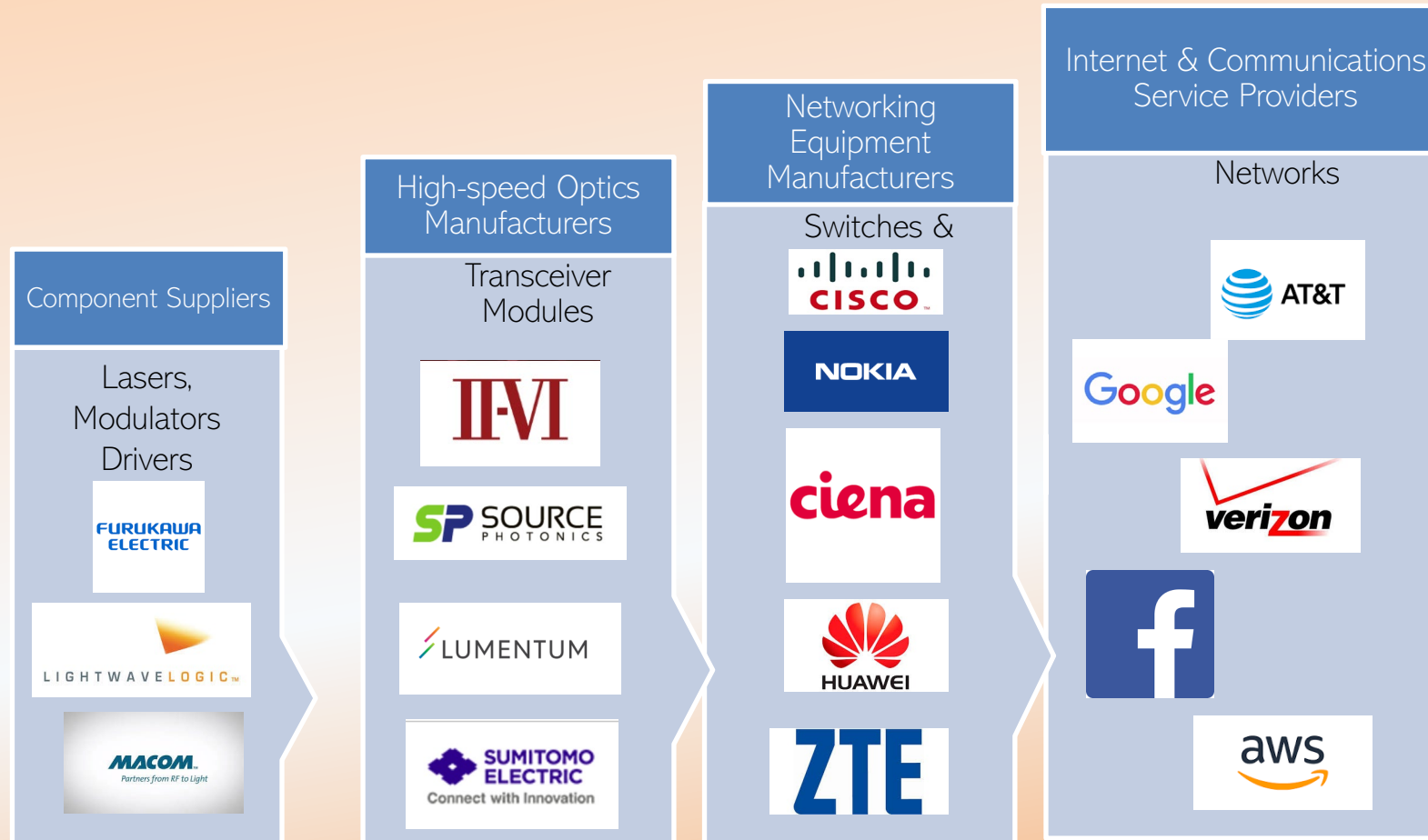
Market Environment: Quick Review

Value chain optical networking



Many market researchers describe big markets today

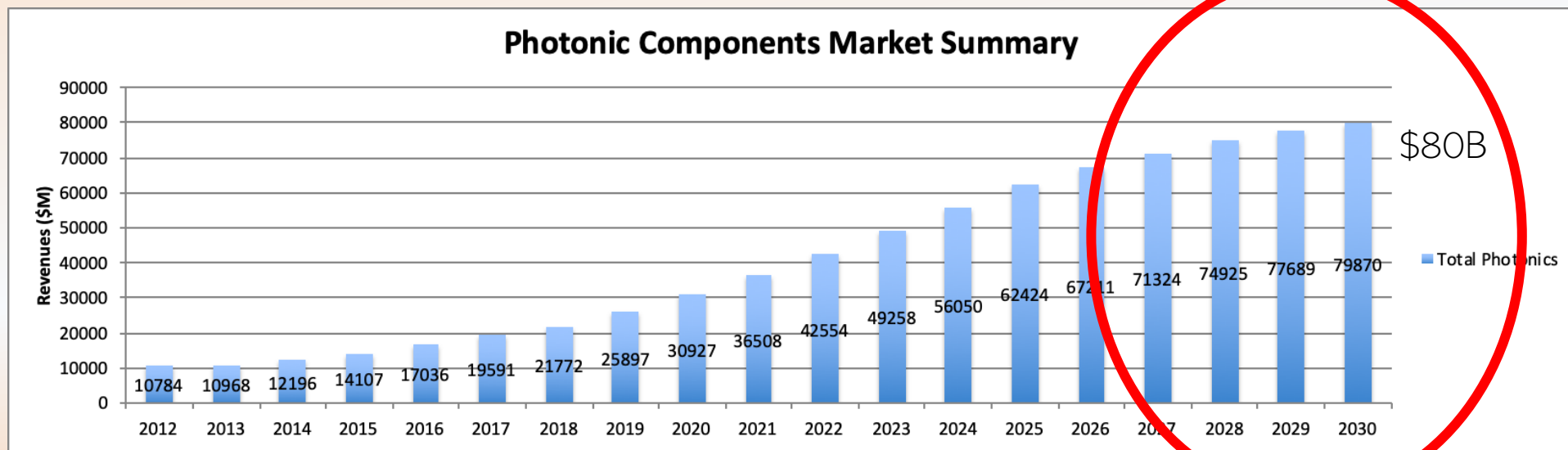
Sample actors in the market place



All want to *understand the impact* of PICs in their network

Summary photonics components market

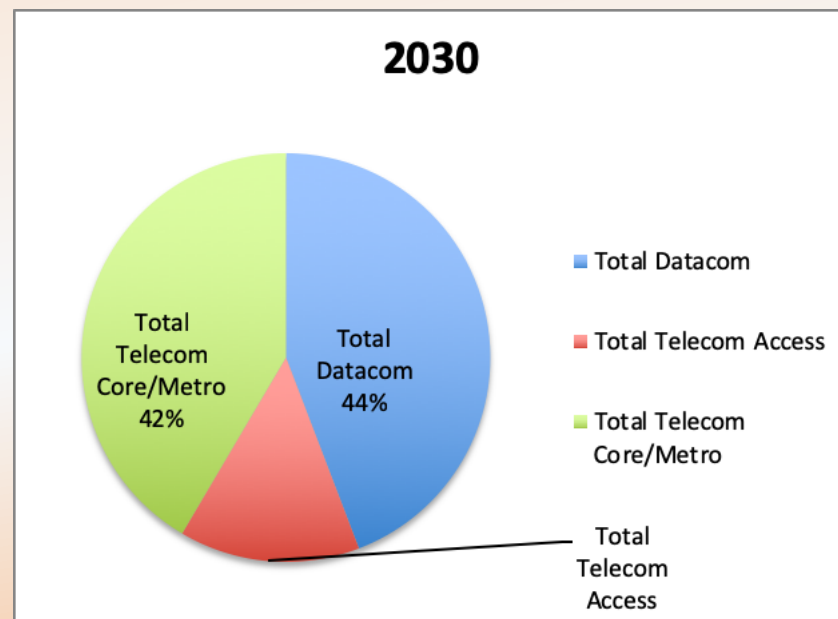
- Photonics components are forecasted to achieve \$80B in 2030 with 17% CAGR (20-30)
- Fiber optic communications



Strong growth forecasted over next decade

Decade perspective in photonics

- By 2030 photonics components will be split evenly between datacom and telecom core/metro
 - Datacom \$35B (22% CAGR); telecom \$33B 13% CAGR)

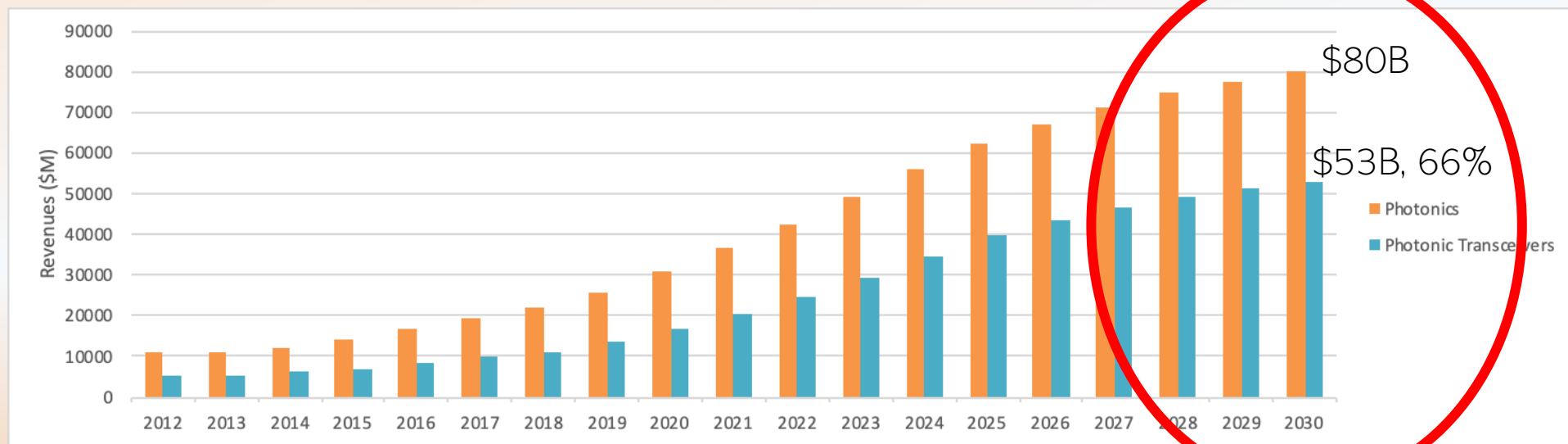


Datacom driven by more aggressive growth



Role of FO transceivers next decade

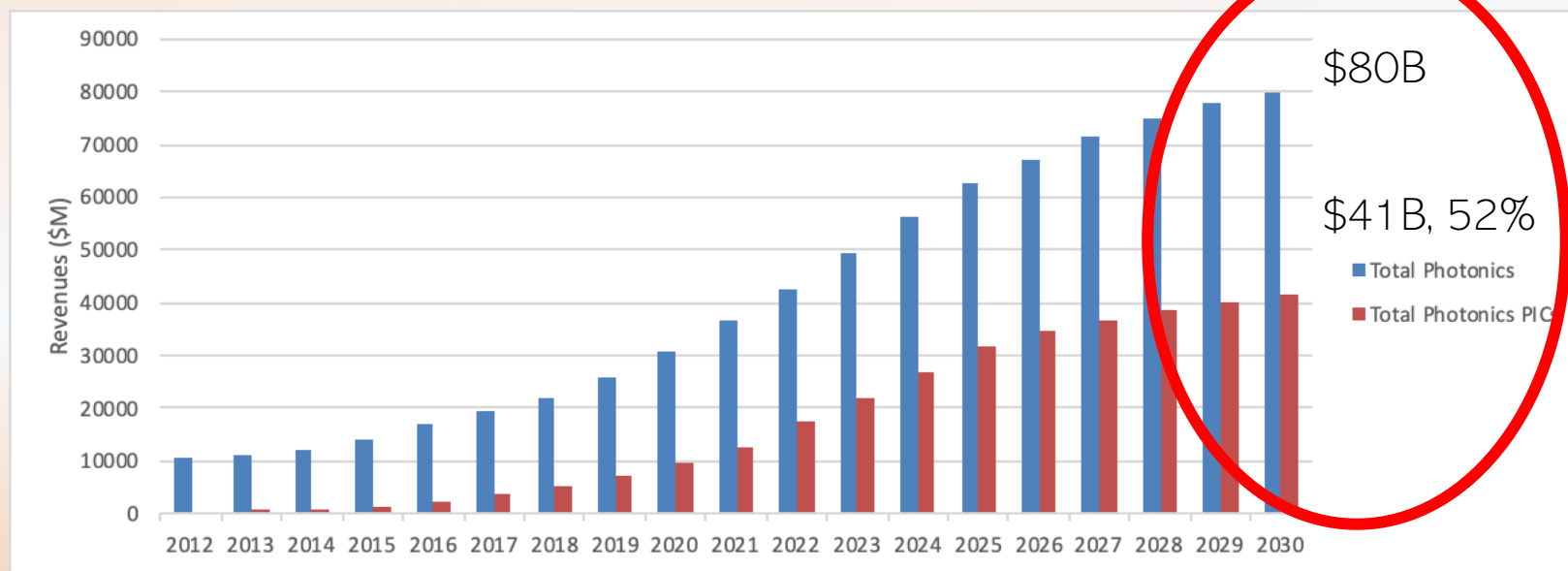
- Photonics components forecast \$80B in 2030
 - 17% CAGR (20-30)
- Photonics transceivers forecast \$53B in 2030
 - 21% CAGR (20-30)



Fiber optic transceiver platform continues to grow well

Forecast of PIC photonic components

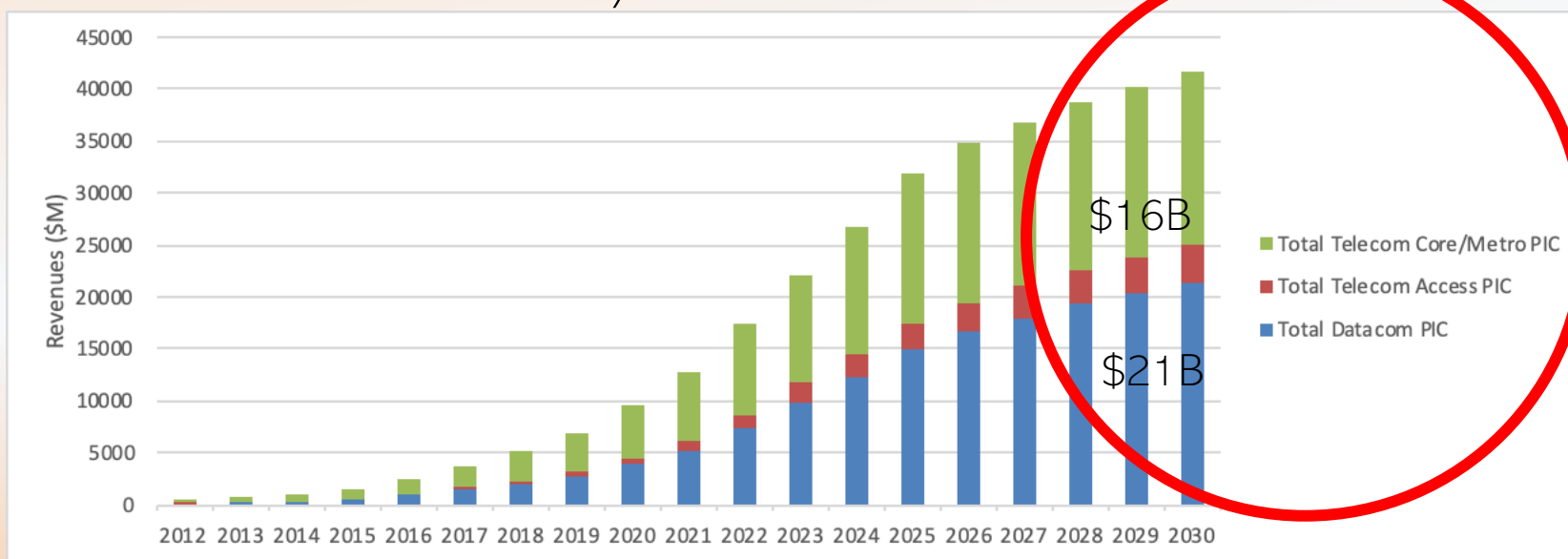
- PIC technologies ~\$41 B by 2030 with 29% CAGR (20-30)
 - PICs include InP, GaAs, SiP, PLC, Polymer reach 52% by 2030
 - PICs are expected to be hybrid solutions
 - PICs composed of datacom, telecom core/metro, telecom access



PIC based technologies **established** over next decade

Decade forecast of PICs

- PIC technologies ~\$41 B by 2030
 - Datacom forecast dominant and grows to \$21 B by 2030 with 29% CAGR (20-30)
 - Telecom core/metro forecast slower and grows to \$16B by 2030 with 28% CAGR 20-30)

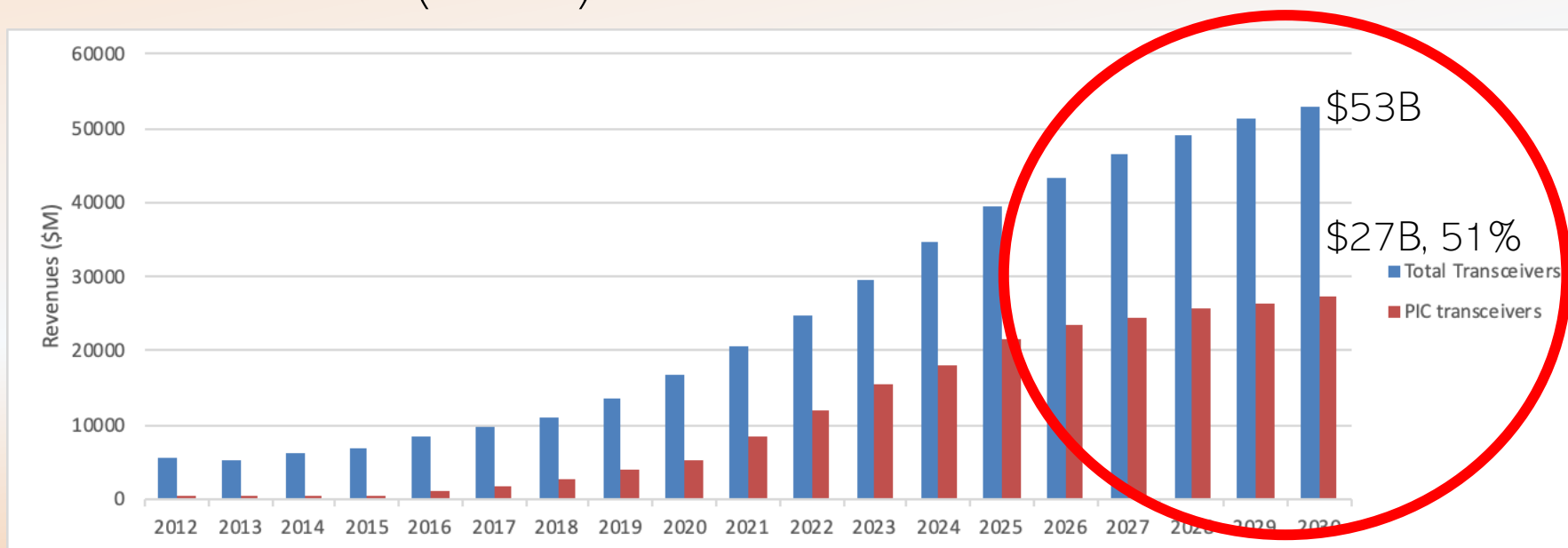


PICs driven by telecom core/metro and datacom



Forecast of PICs in transceivers

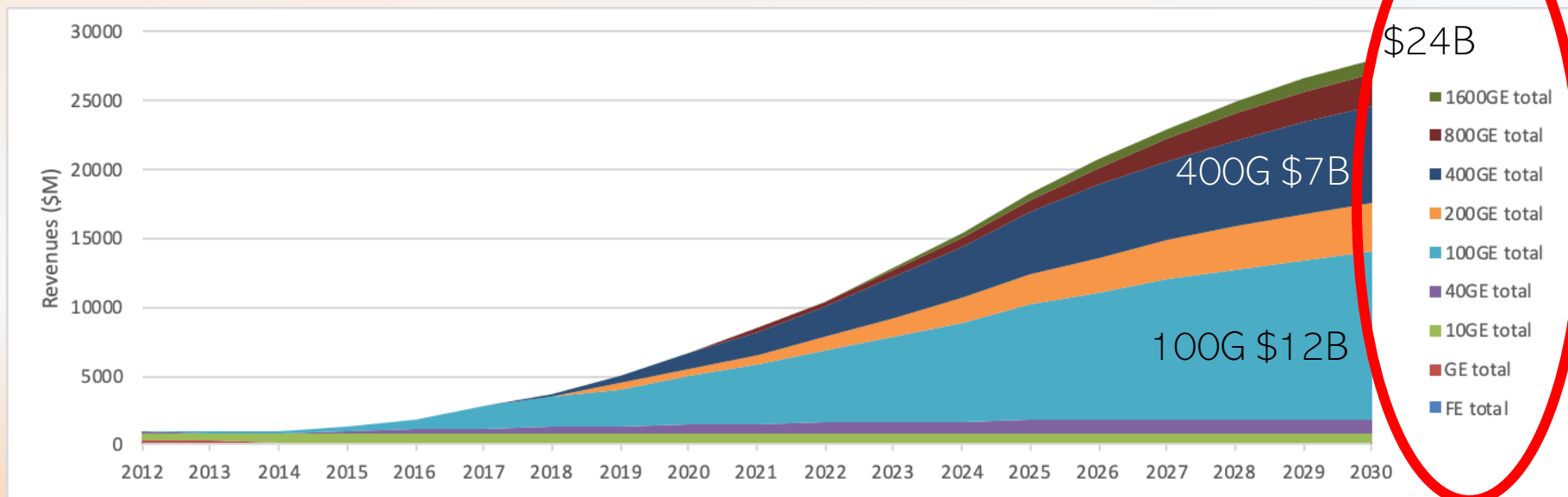
- Transceivers reach ~\$53B by 2030
 - 21% CAGR (20-30)
- PIC TxRx forecasted to reach \$27B by 2030
 - 31% CAGR (20-30)



PICs will become half of the transceiver mkt by 2030

Forecast of Ethernet by datarate

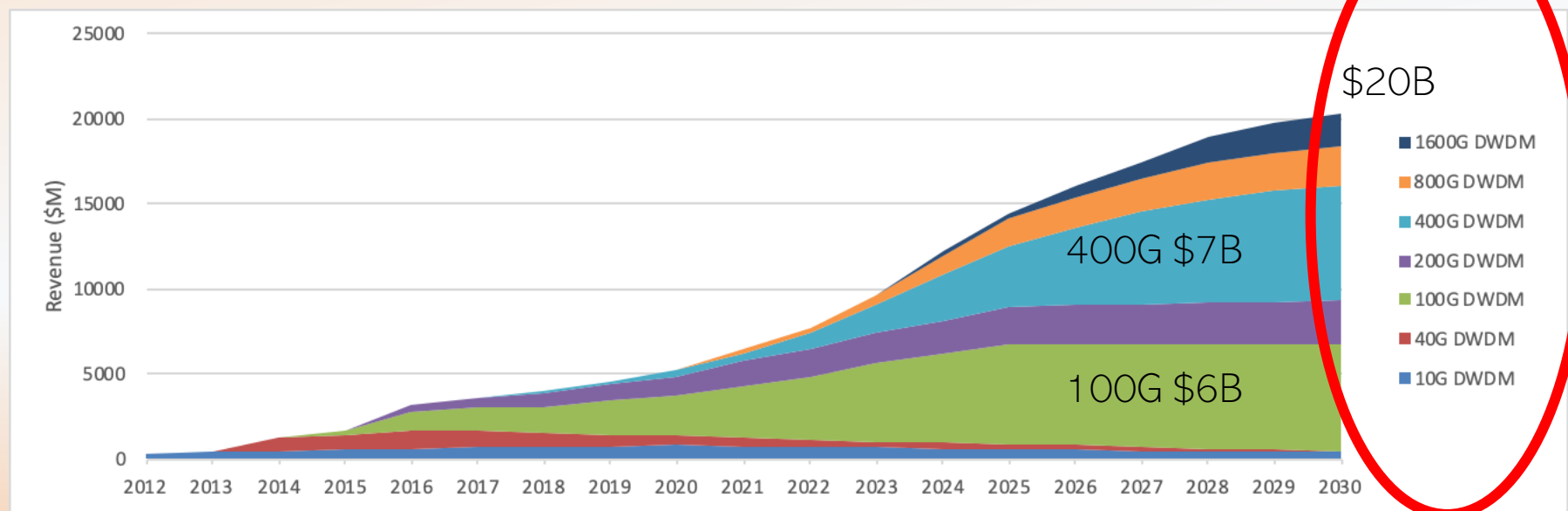
- Ethernet TxRx reach ~\$28B by 2030
 - 27% CAGR (20-30)
 - Ethernet TxRx driven by 100G and 400G platforms
 - Increasing datarate to 800G and 1600G over decade



Datarate for Ethernet TxRx continues to climb to 1600Gbps

Forecast of DWDM TxRx by datarate

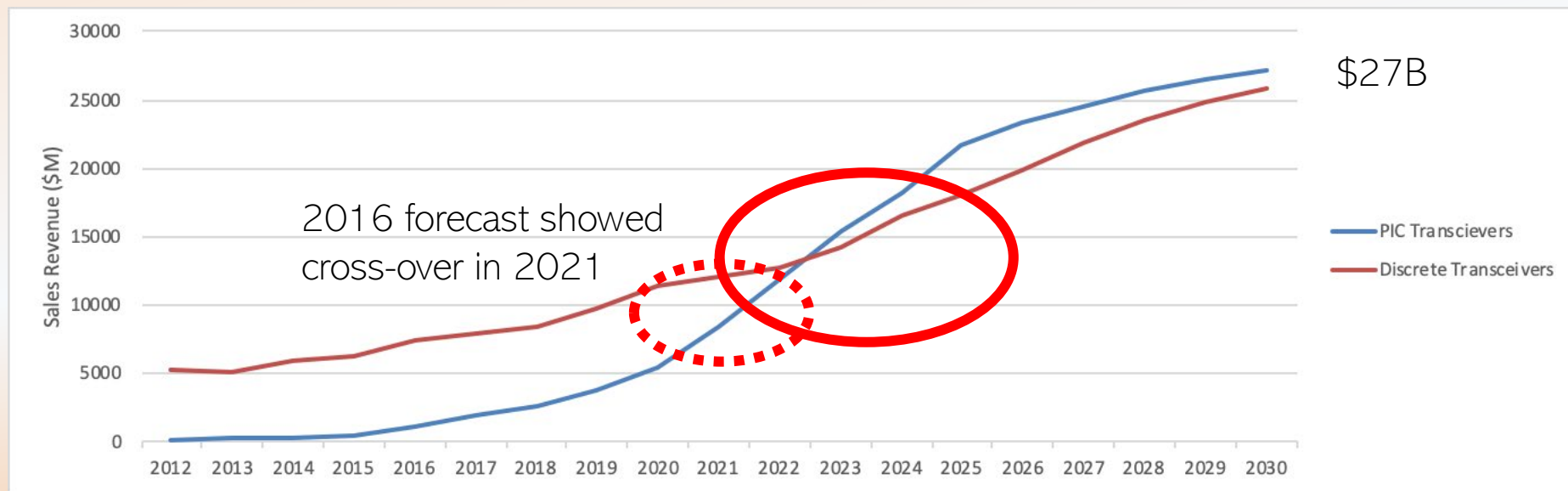
- DWDM TxRx reach ~\$20B by 2030
 - 27% CAGR (20-30)
 - DWDM TxRx driven by 100G and 400G platforms
 - Increasing datarate to 800G and 1600G over decade



Datarate for DWDM TxRx also climbs to 1600Gbps

Important PIC metrics...

- PIC TxRx forecast against discrete TxRx to 2030
 - PIC based TxRx are expected to reach \$27B in 2030
 - PIC based technologies lead the segment by end of decade



Slower pick-up of PIC transceivers in 2019 forecast



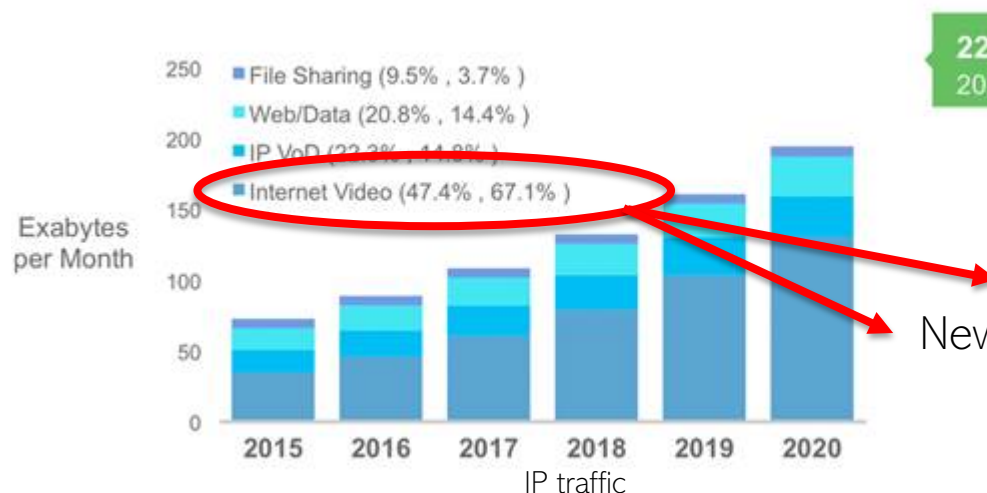
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Market Environment: Growing gap



Everyone knows this...



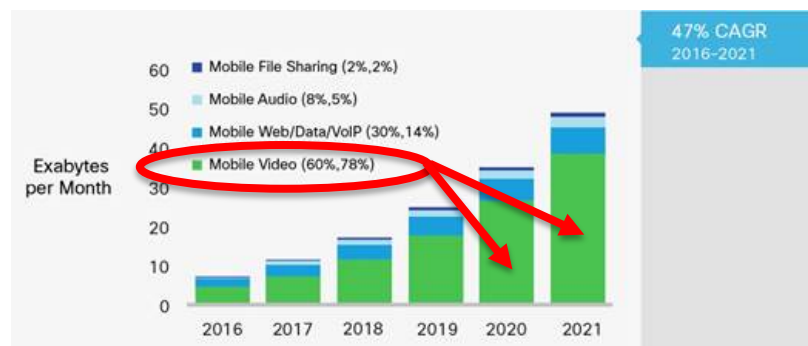
Traffic per End User

Old phone Kbps \rightarrow Kilo = 10^3

Old "broadband" Mbps \rightarrow Mega = 10^6

New home Gigabit broadband \rightarrow Giga = 10^9

X More End Users



Traffic yesterday \rightarrow Peta = 10^{15}

Traffic today \rightarrow Exa = 10^{18}

Traffic tomorrow \rightarrow Zetta = 10^{21}

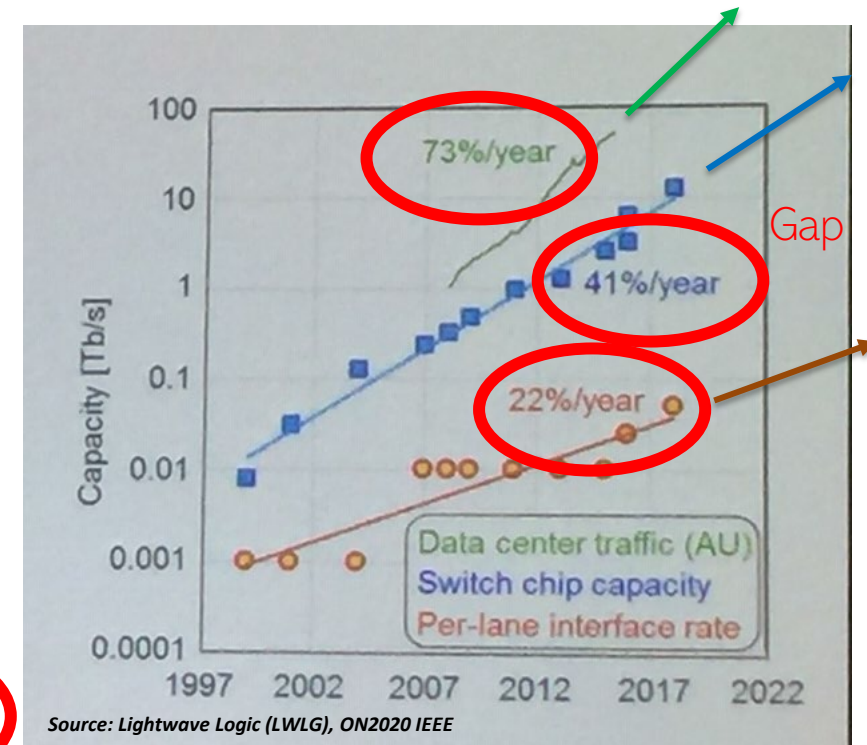
Coming soon \rightarrow Yotta = 10^{24}

Total Internet Traffic

Video has driven massive growth, and continues to increase

Market gap in the network is a challenge

- Network speeds lagging
 - Growing at only half the rate as computing and switching electronics
 - Gap has been growing for decades!
- Now the network is starting to limit cost, power and scalability of datacenters
- Business as usual is not going to keep services and the internet growing



Theme – we will need to *radically innovate* to reduce the gap...



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Market technology opportunities



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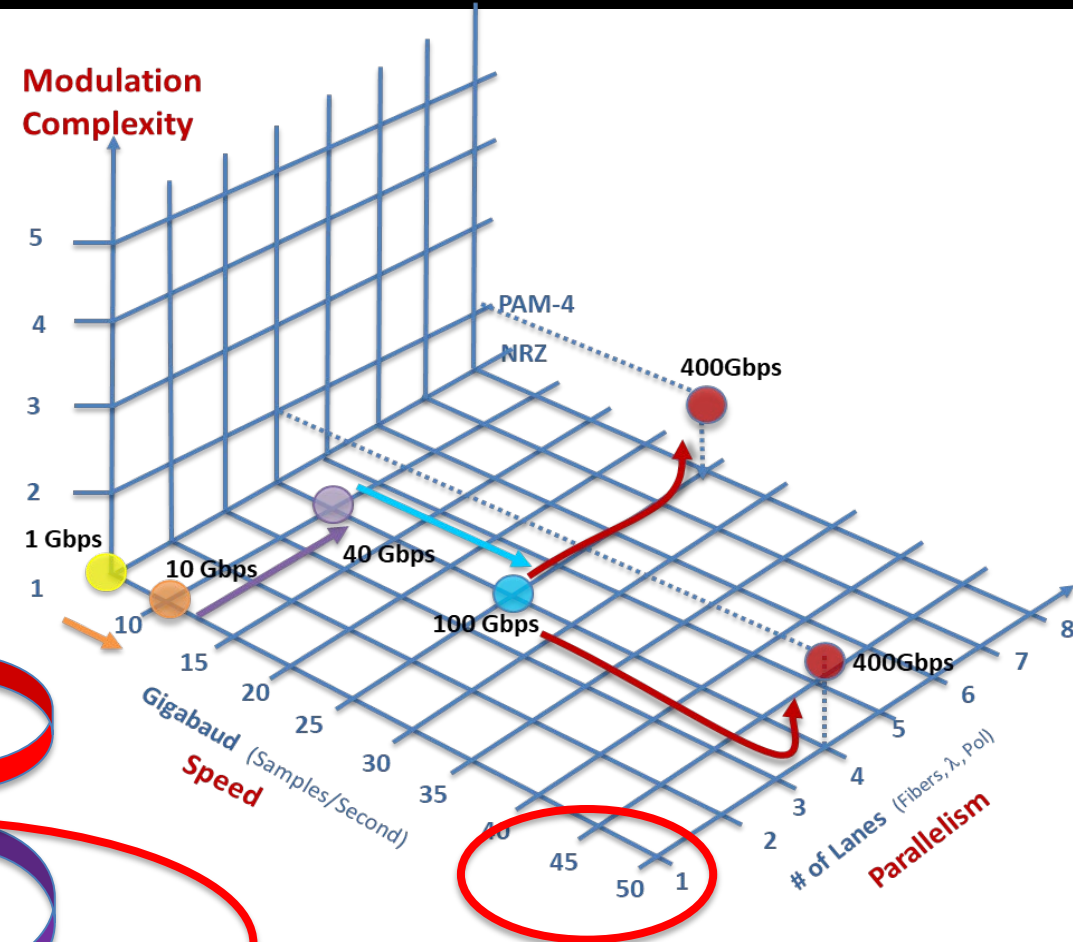
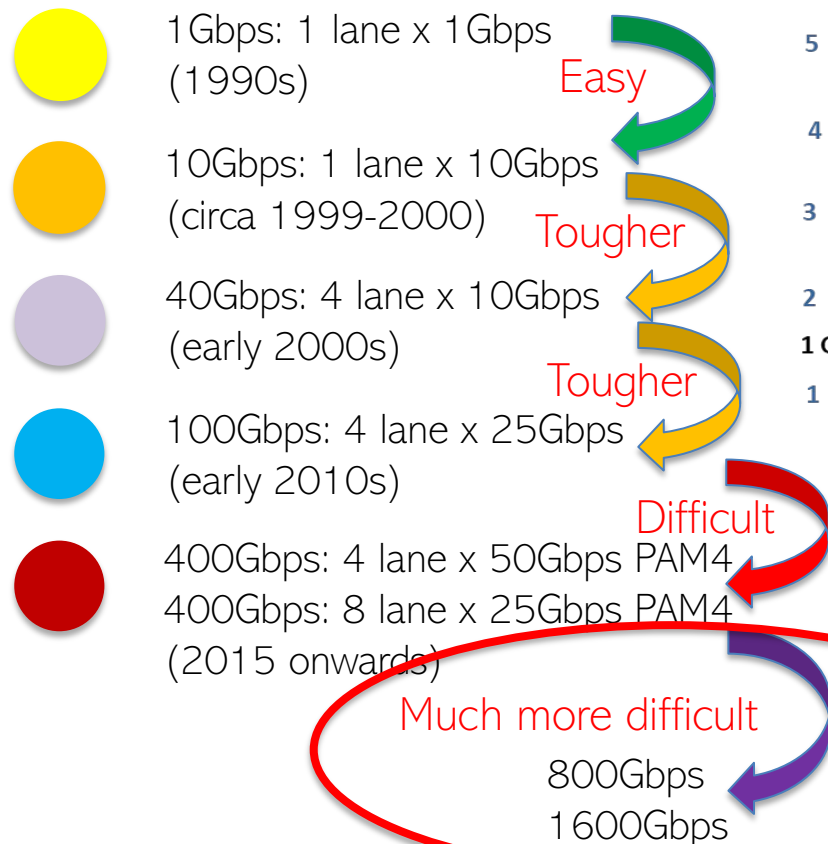
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Faster devices...



But the internet has been growing
fine, so what's changed?

Historical perspective



Things get tougher with increasing data rates

Traffic capacity: road analogy

Good roads: Faster cars:
more traffic capacity



More lanes: more traffic capacity



Already did the easy things like paving the road and adding more lanes

Traffic handling: road analogy



Industry has already done the **harder stuff** like 'higher order modulation'

What about speed?



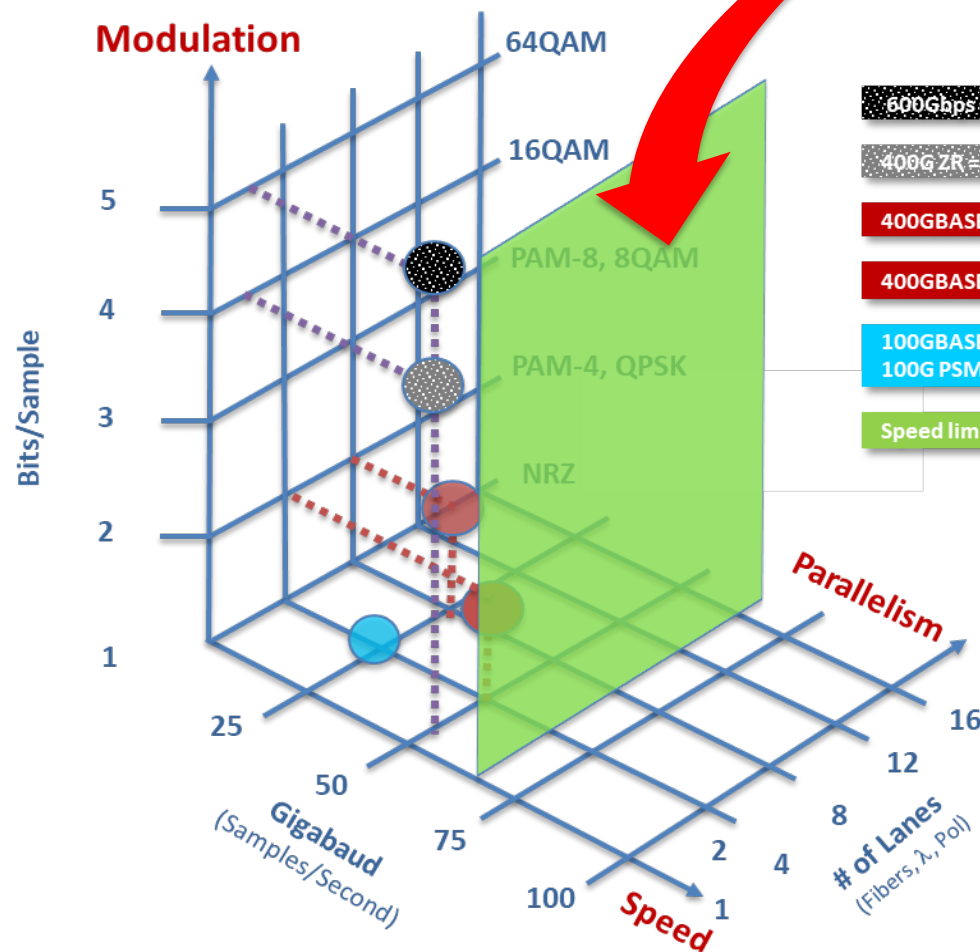
10 mph → 60 mph



Still ~60 mph

Speed has hit a plateau...

Speed limited by conventional photonics



600Gbps = 64 Gbaud, 64QAM, 2 polarizations

400G ZR = 50 Gbaud, 16QAM, 2 polarizations

400GBASE-DR4/ 400G FR4 = 50 Gbaud, PAM4, 4 wavelengths

400GBASE-LR8 = 25 Gbaud, PAM4, 8 wavelengths

100GBASE-LR4/100G CWDM4 = 25 Gbaud, NRZ, 4 wavelengths

100G PSM4 = 25 Gbaud, NRZ, 4 fibers

Speed limitation of optical devices



50 Gbaud is very difficult for conventional optical devices

Speed limited by device physics

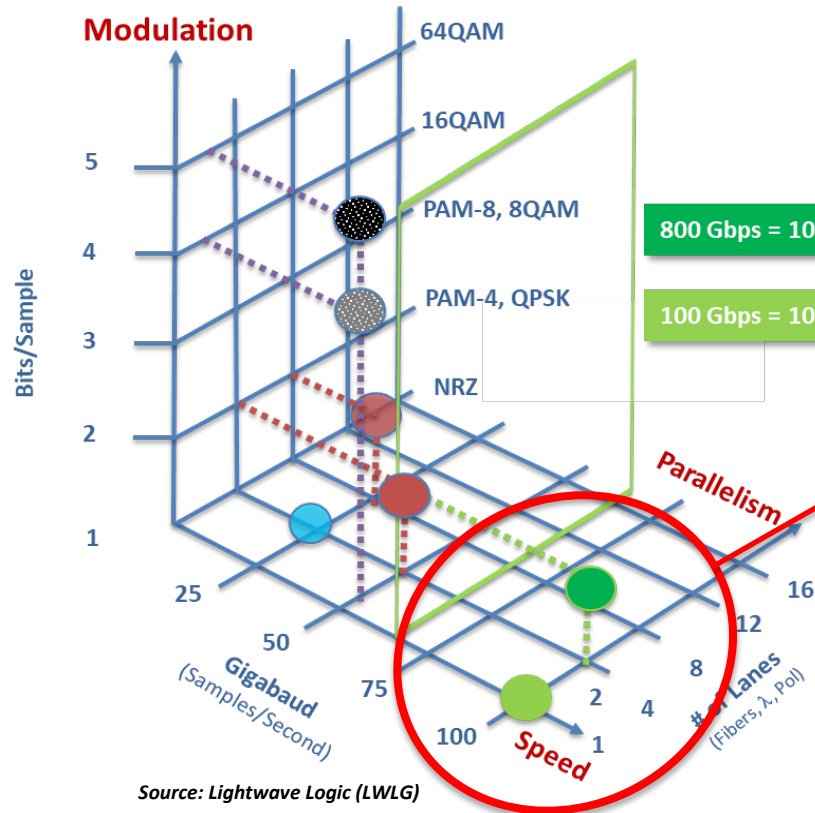
Plastic polymers break the speed limit...



Polymers are faster than other technologies

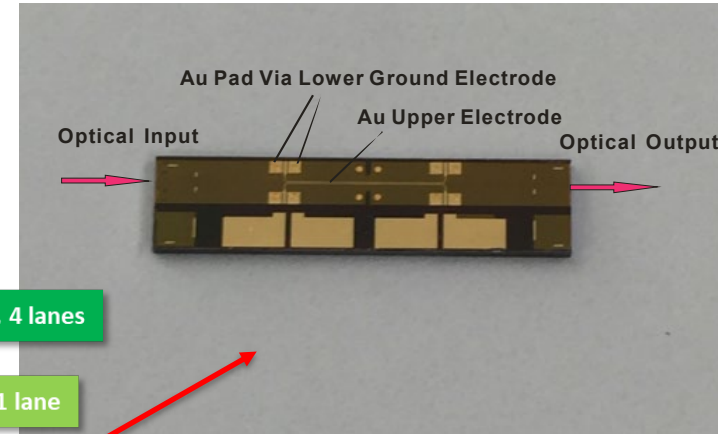
Polymers double the native data traffic to 100Gbps (before counting multiple lanes, stacking...)

Innovation to break the speed barrier



800 Gbps = 100Gbaud, PAM4, 4 lanes

100 Gbps = 100 Gbaud, NRZ, 1 lane



- Options can be:
- 100G, 1V
 - 100Gbaud, NRZ, OOK
- 400G, 1V
 - 4 Channel x 100G NRZ, OOK
- 800G, 1V
 - 4 Channel x 100G, PAM-4

Renewed ability to grow traffic capacity



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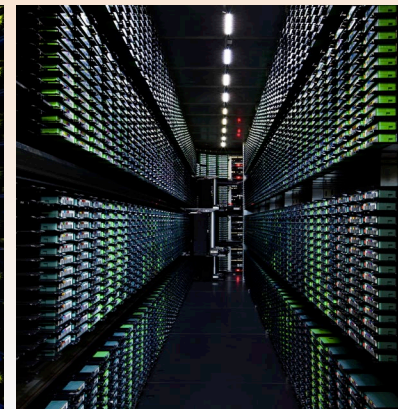
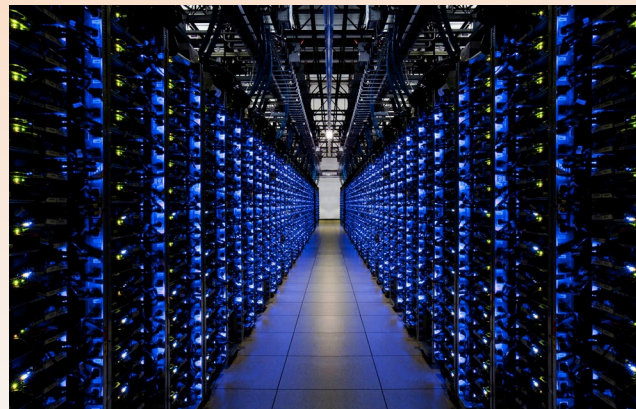
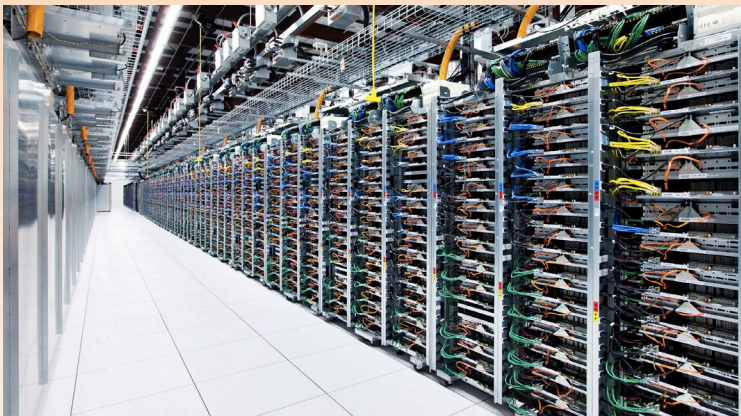
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Lower power



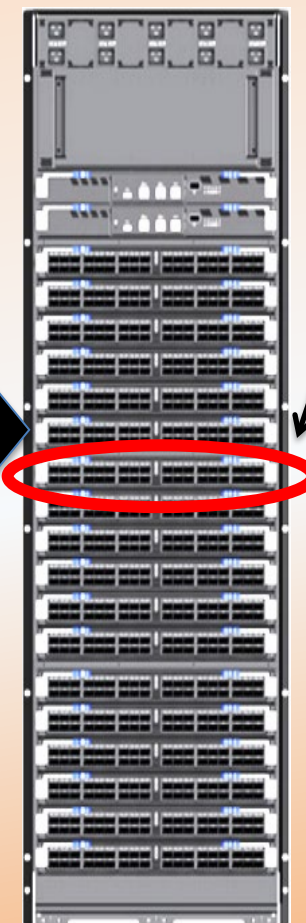


Everyone knows this too...



Power is limiting datacenter growth

Drive to greater density



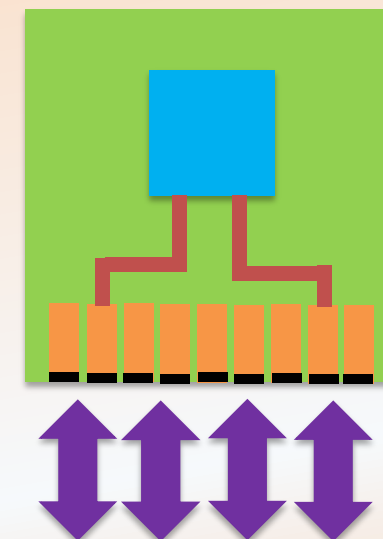
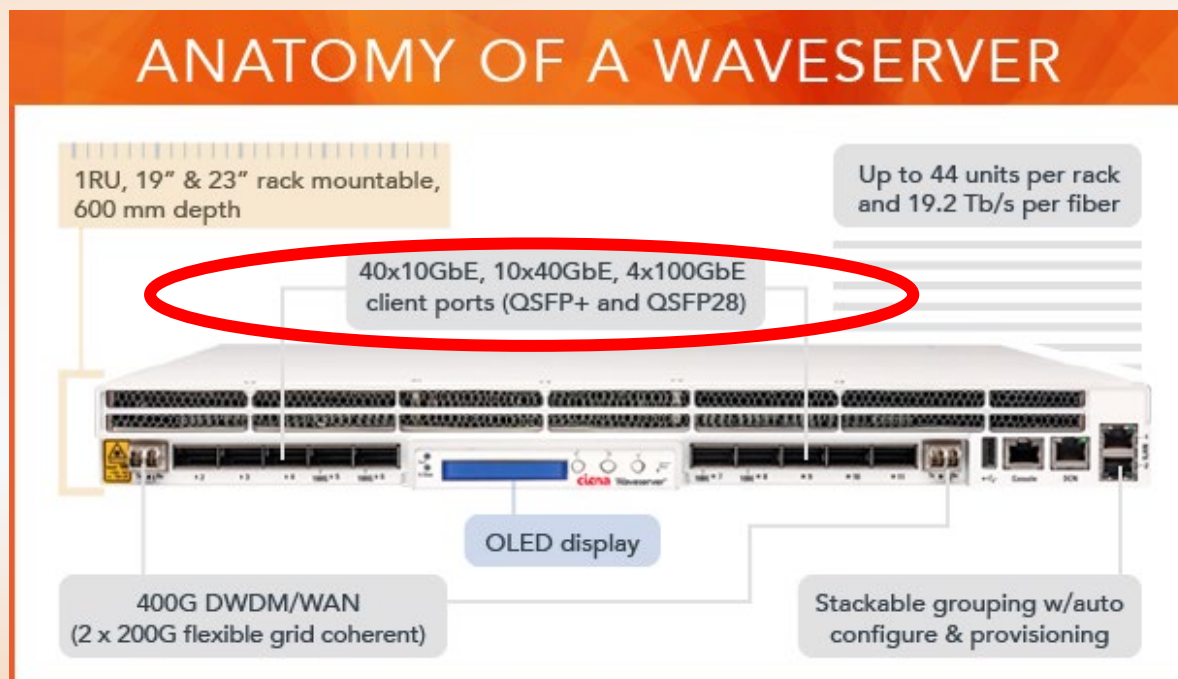
Equipment capacity is limited by how many transceivers can fit on the faceplate

Faceplates are where traffic enters and exits in the datacenter



Denser faceplates means smaller optics

- Customers are requesting 50-100 Tbps solutions
- This faceplate is only 1.2 Tbps!

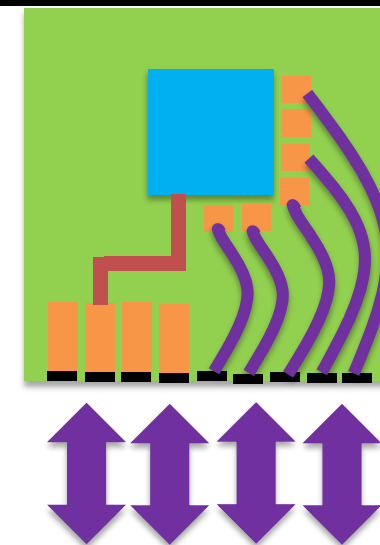
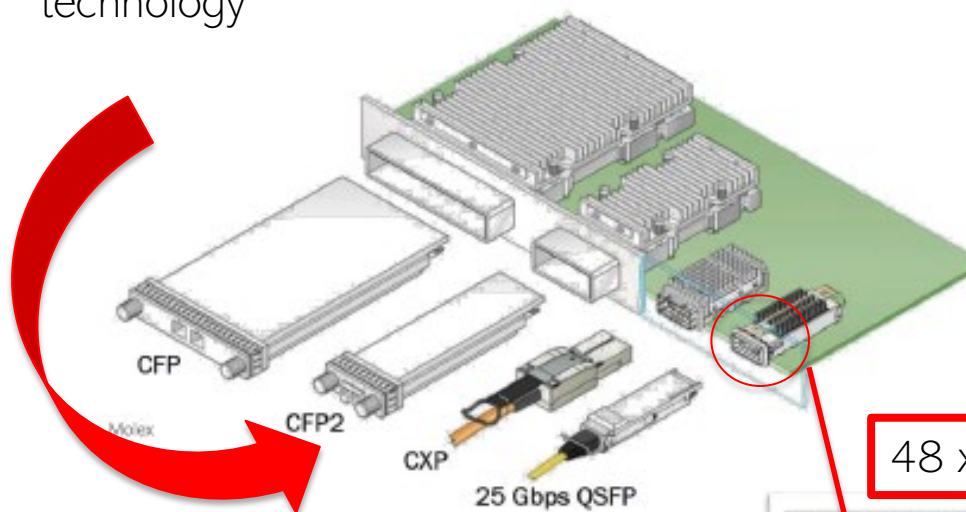


Incremental improvements won't give the **100x increase**



Are pluggables reaching a limit?

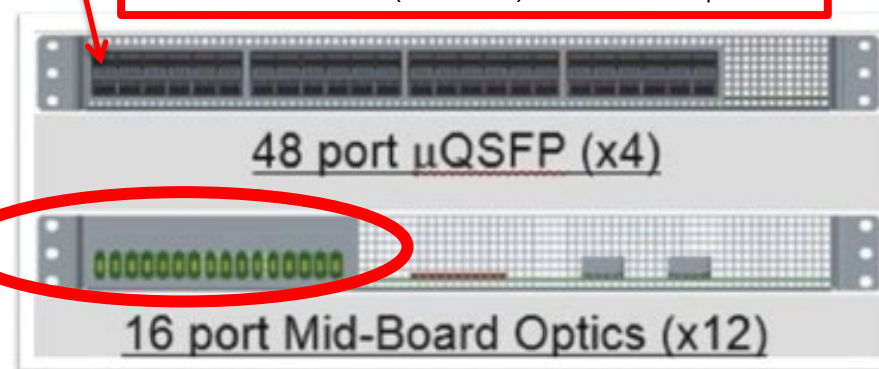
Transceiver boxes have been shrinking quickly... which *opens opportunities* for polymer based technology



Top View

48 x uQSFP (100G) = 4.8Tbps

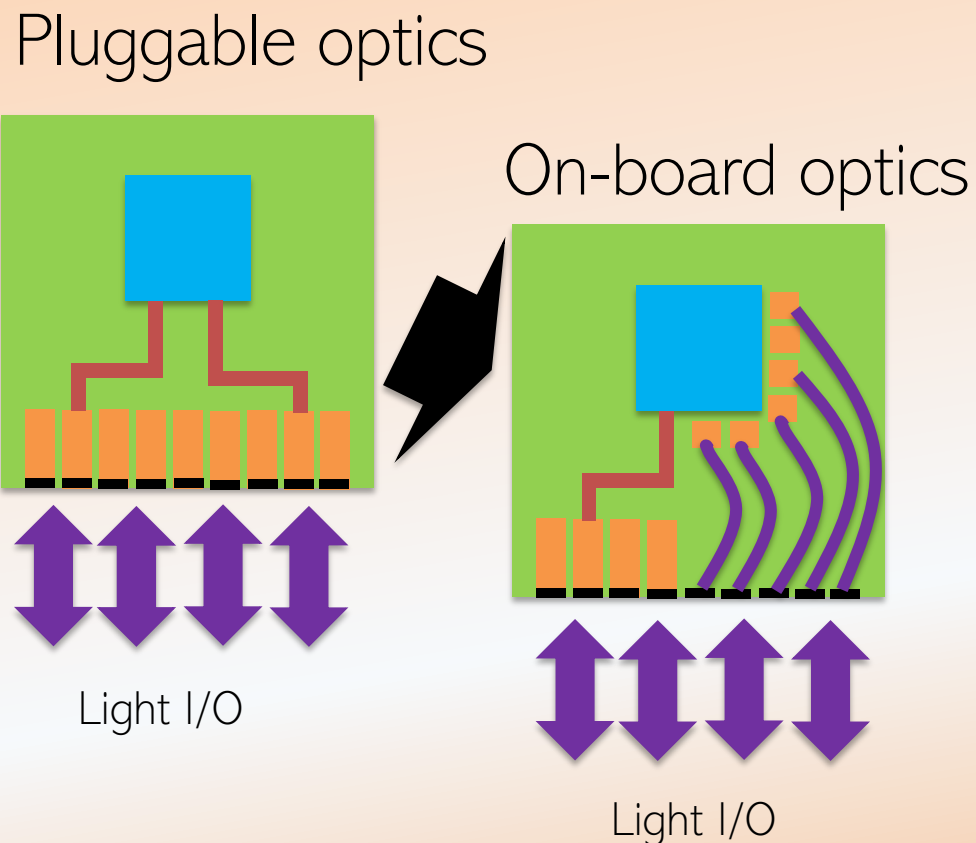
By using 16 fibers to connect TxRx on board then more room on faceplate for cooling



Standard 1RU faceplate with 48 ports

Combination – fiber on-board optics and pluggable?

Trend today: pluggable → on-board



- Pluggable optics
 - Limit in physical size of pluggable boxes
- On-board optics
 - Stepping stone to bringing optics closer to the switch electronics

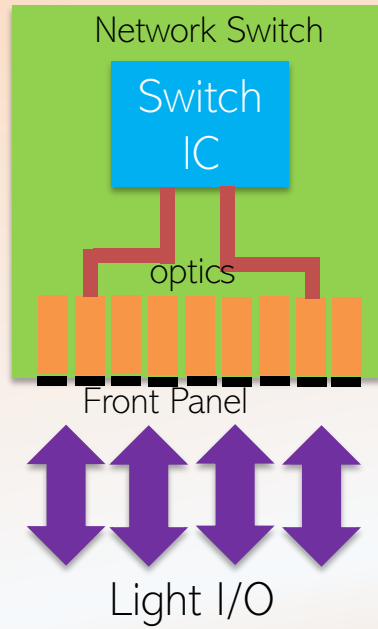
Will these solutions suffice for 100Tbps+ ?

Co-package the optics...

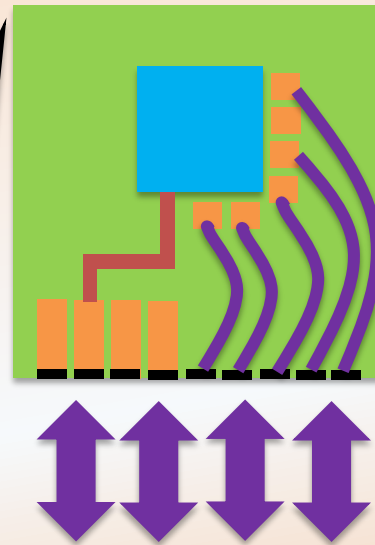
Top View

Pluggable optics

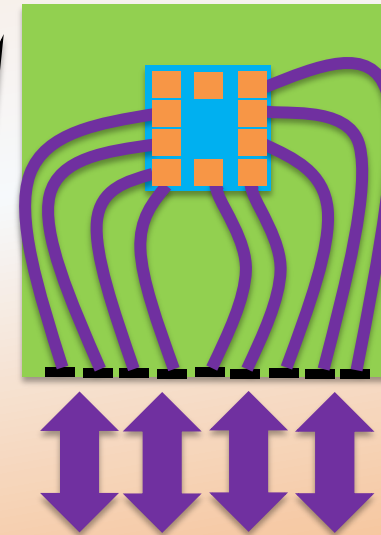
Pluggables are too big, and too far from the switch IC



On-board optics



Co-packaged optics



Co-packaging is a hybrid integration opportunity for polymer photonics

Trend: move from TxRx to multi-chip modules (MCM) like electronics did 25 Yrs ago



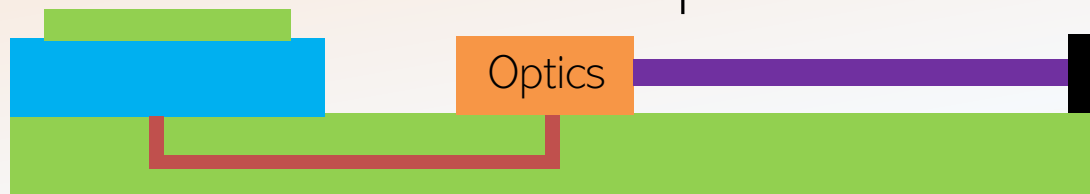
Co-packaging – full integration

Side View

Pluggable optics



On-board optics

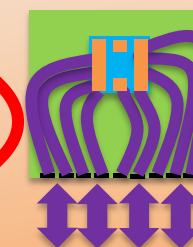
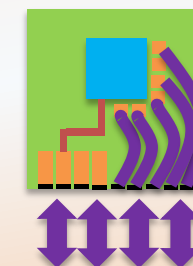
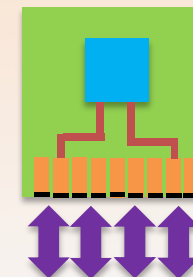


Co-packaged optics



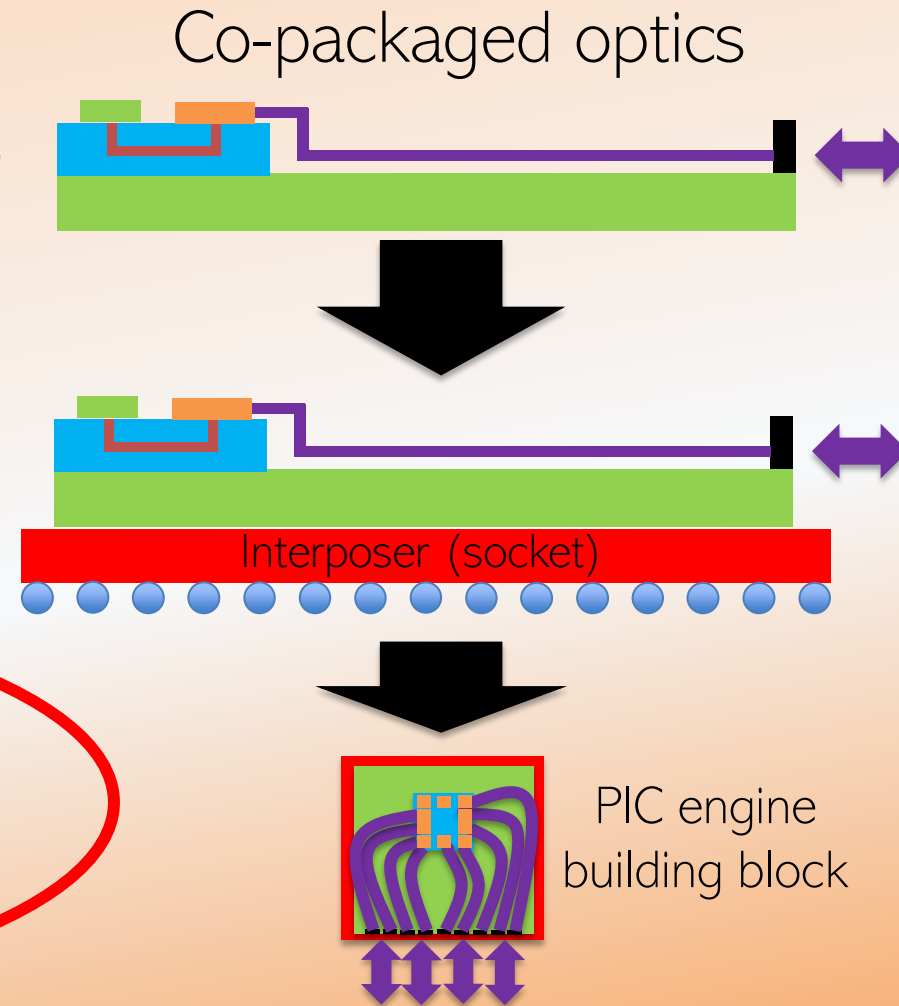
True photonic integration – Board scale PIC technology

Top View



Scaling the co-packaged PIC engine

- Current switches support 12.8Tbps I/O
 - 16nm CMOS (e.g. Broadcom Tomahawk 3 switch)
 - Pluggable modules (potential to scale to 25Tbps)
- Next generation needs up to 400Tbps I/O capacity
 - 1kW at 10pJ/bit → huge heat source !!
 - I/O expensive, power prohibitive
- Customers want
 - 100Tbps, scaling to 400Tbps I/O capacity
 - <5pJ/bit (to keep power in check)
 - Smaller size → miniaturization
 - Perhaps a different solution?



Side View

Top View

Co-packaging optics enables high traffic throughput



Co-packaging open questions

- Co-packaging now viewed as inevitable
 - Not clear how to get there – higher levels of integration
 - Ecosystem will change significantly as technology will change
 - From OFC2019, “the future has never been as fuzzy”
- Route to 400Tbps using 800/1600Gbps
 - Not an extrapolation; not just an extension of what has been done before
- *Co-packaging is different...*

New challenges bring *new opportunities* for PICs



Route to multi-100Tbps PCP-MCM

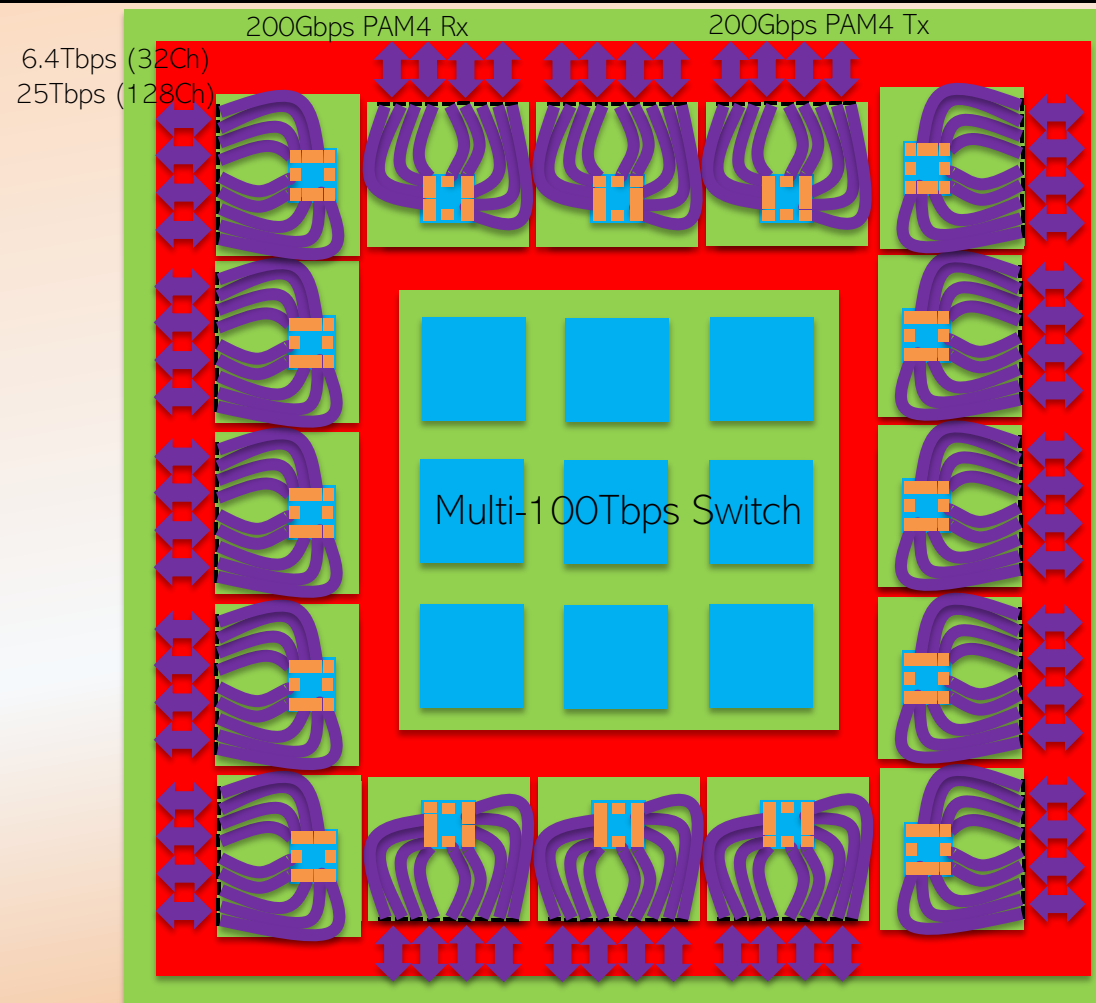
Polymer Co-Packaged Multi-Chip Module

Use of polymer (organic PCB) technology throughout

Passive waveguides, coupling, boards

Active modulators

- Polymer passives
 - Waveguide interface
- Polymer 80GHz modulators
 - 100Gbps NRZ or
 - 200Gbps PAM4
- 32 channels x 200 Gbps = 6.4 Tbps/PIC engine
X 16 engines = 102.4 Tbps
- 128 channels x 200 Gbps
X 16 engines = 400 Tbps



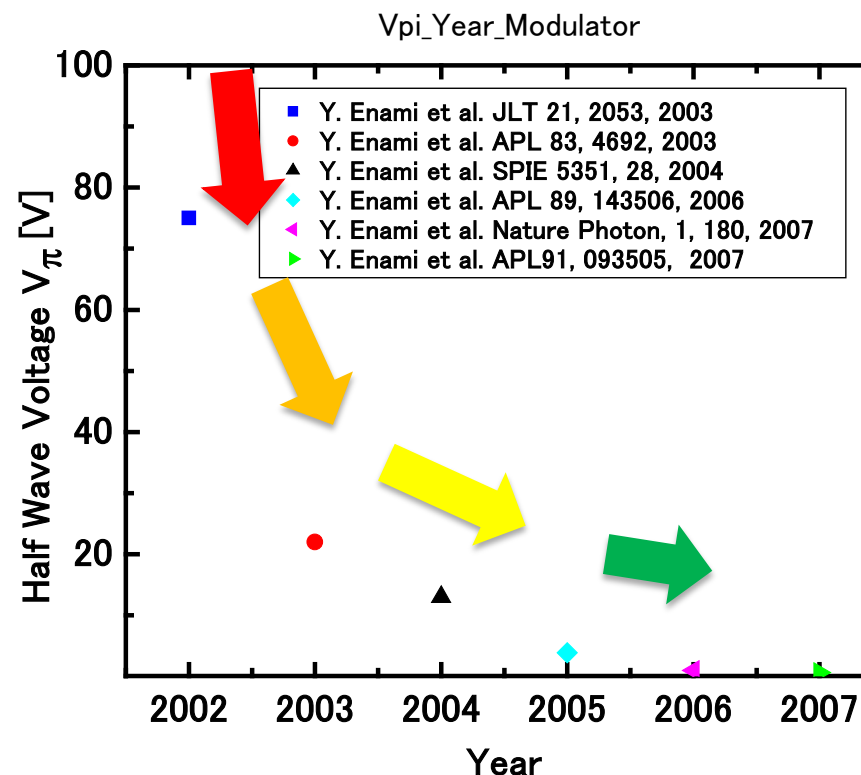
Top View

Polymer PIC engine as building block for 400Tbps solutions



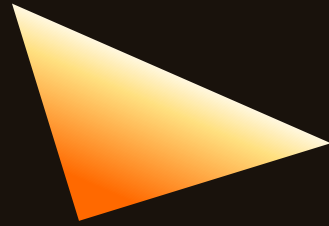
Direct drive CMOS → saves power

- Lower voltage operation save power
- Also means the modulators can be driven directly from a CMOS chip
- No driver chips necessary
 - Saves even more power
 - Also saves \$\$\$



Source: Lightwave Logic (LWLG); Yasufumi Enami (University of Kochi, Japan; University of Arizona)

Polymer modulators are *driverless, low power, and save \$\$\$*



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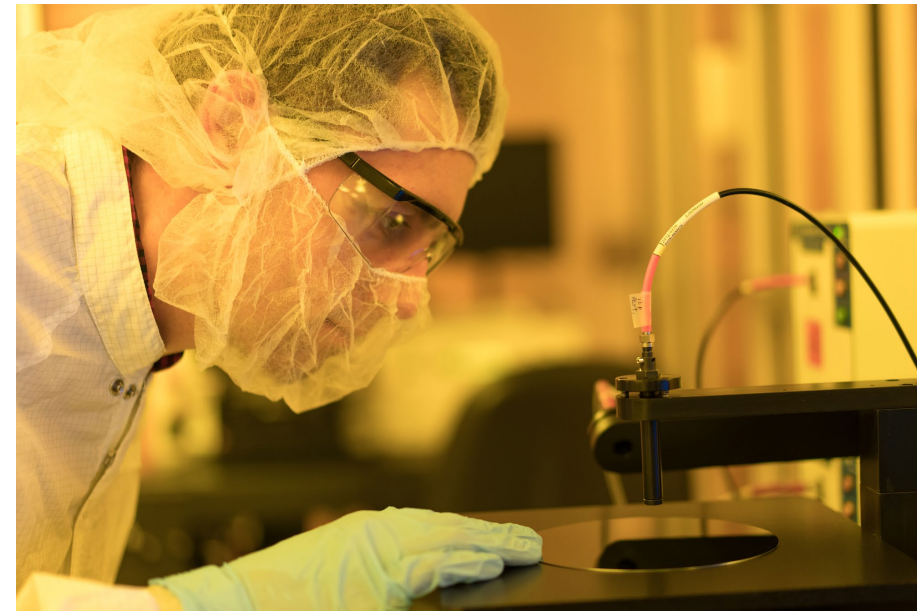
Lower cost...



Simple, low cost fabrication

Fabrication equipment and process is simple

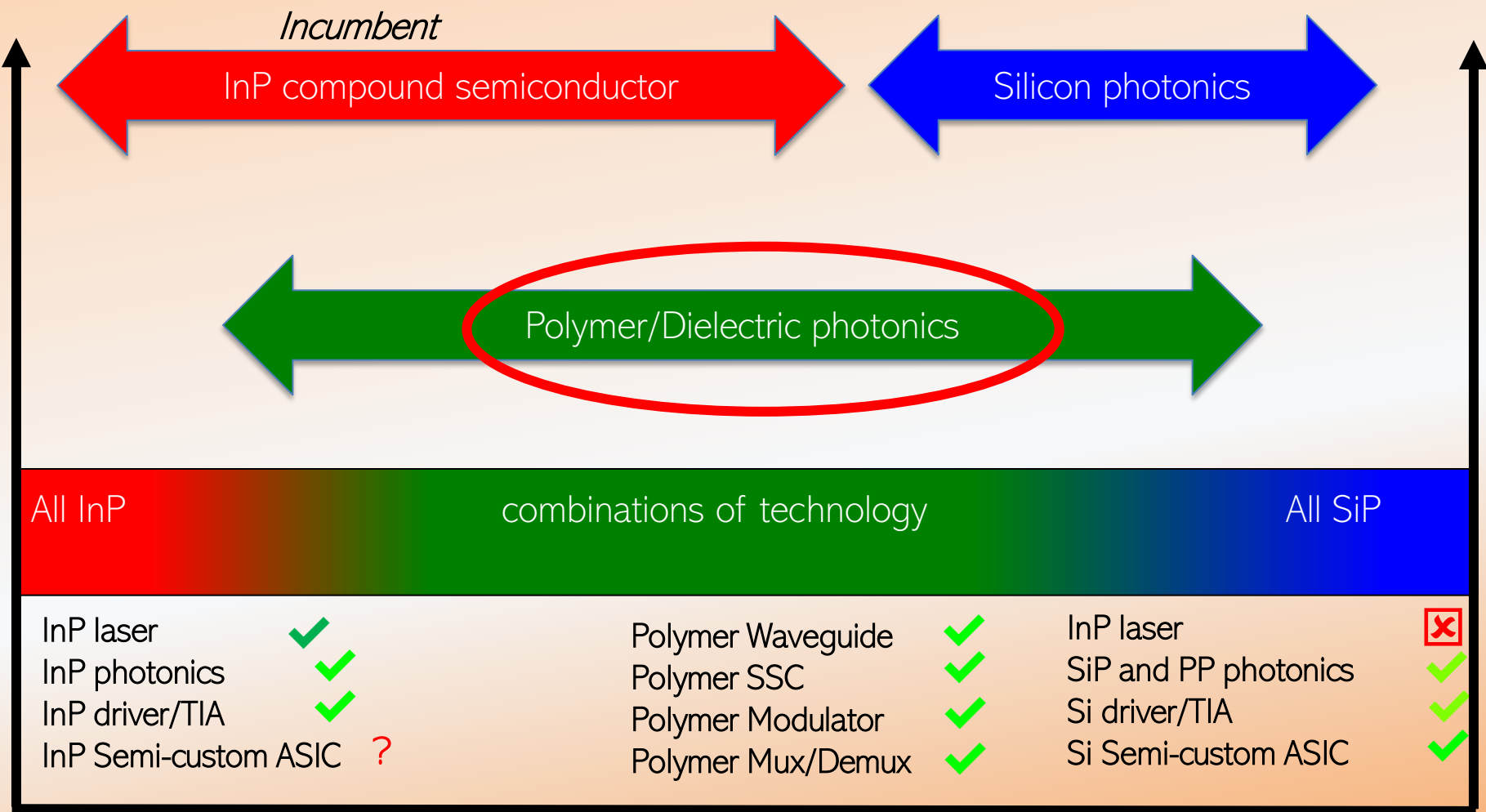
- No exotic equipment needed
 - Standard photolithography to pattern
 - Wafer scalability
 - Minimize cycle time



Lower costs can be enabled through simplicity in fabs



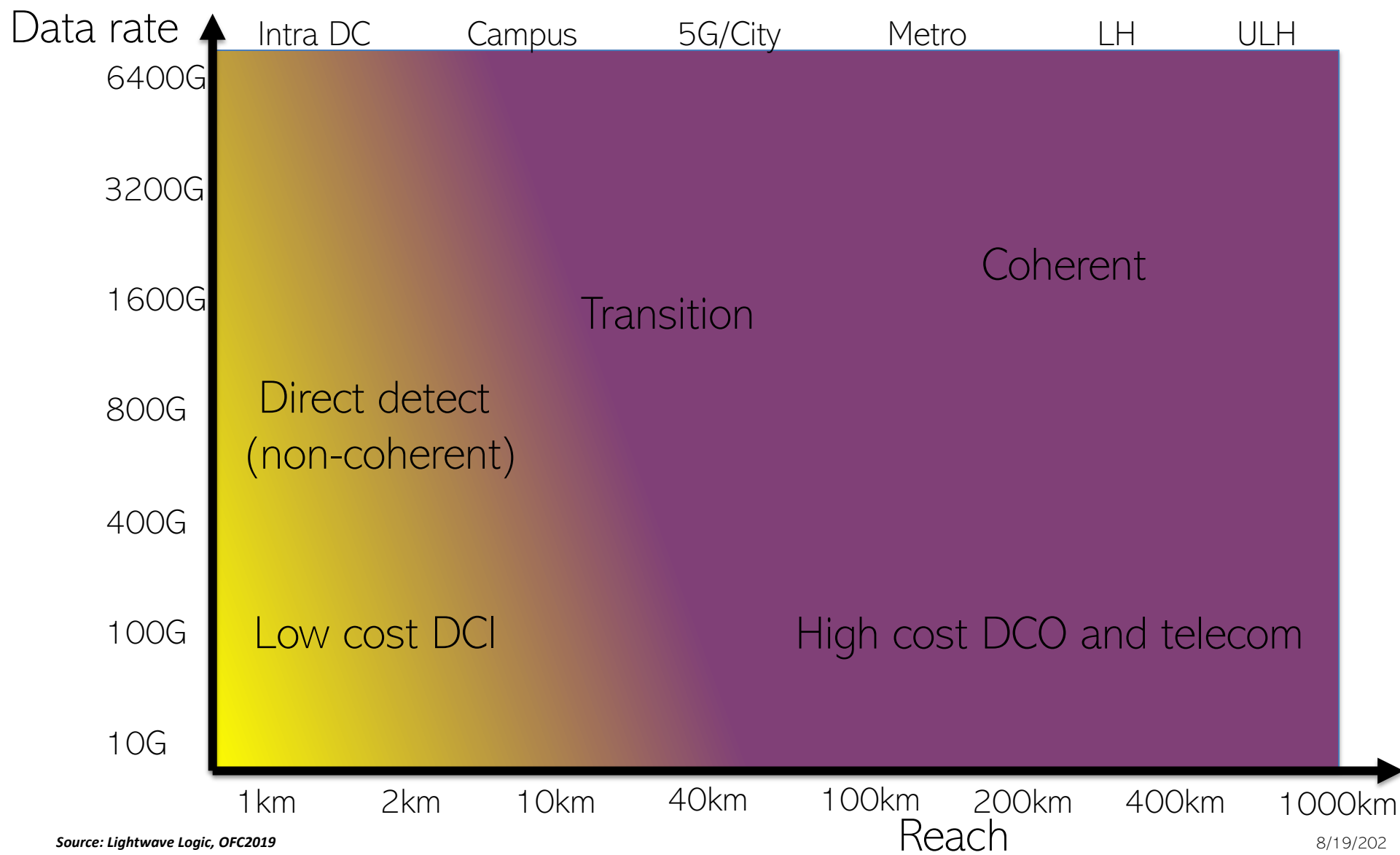
Integrate platforms → Hybrid solutions



Lower costs enabled through integration of hybrid technologies

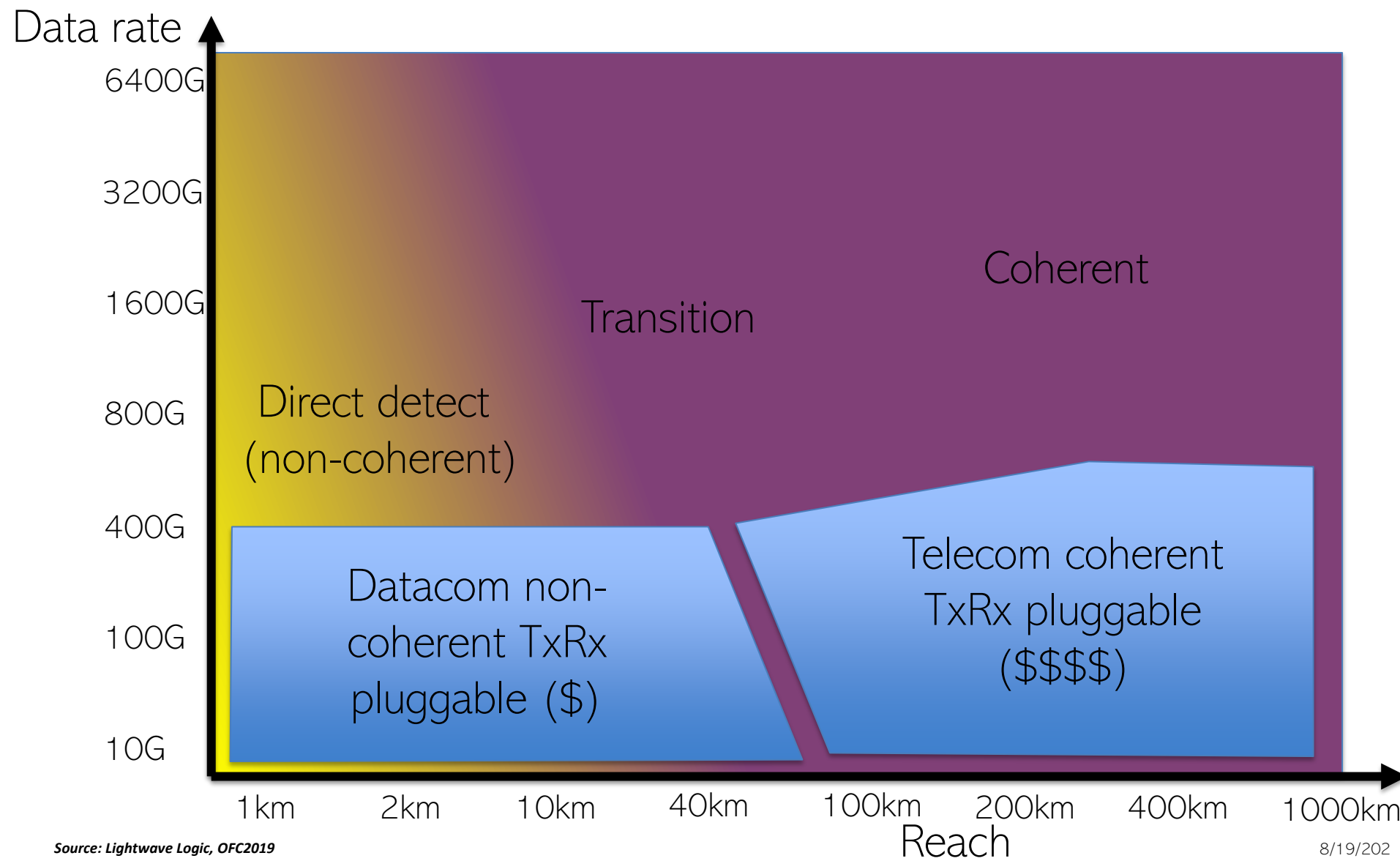


Lower cost via protocol planning



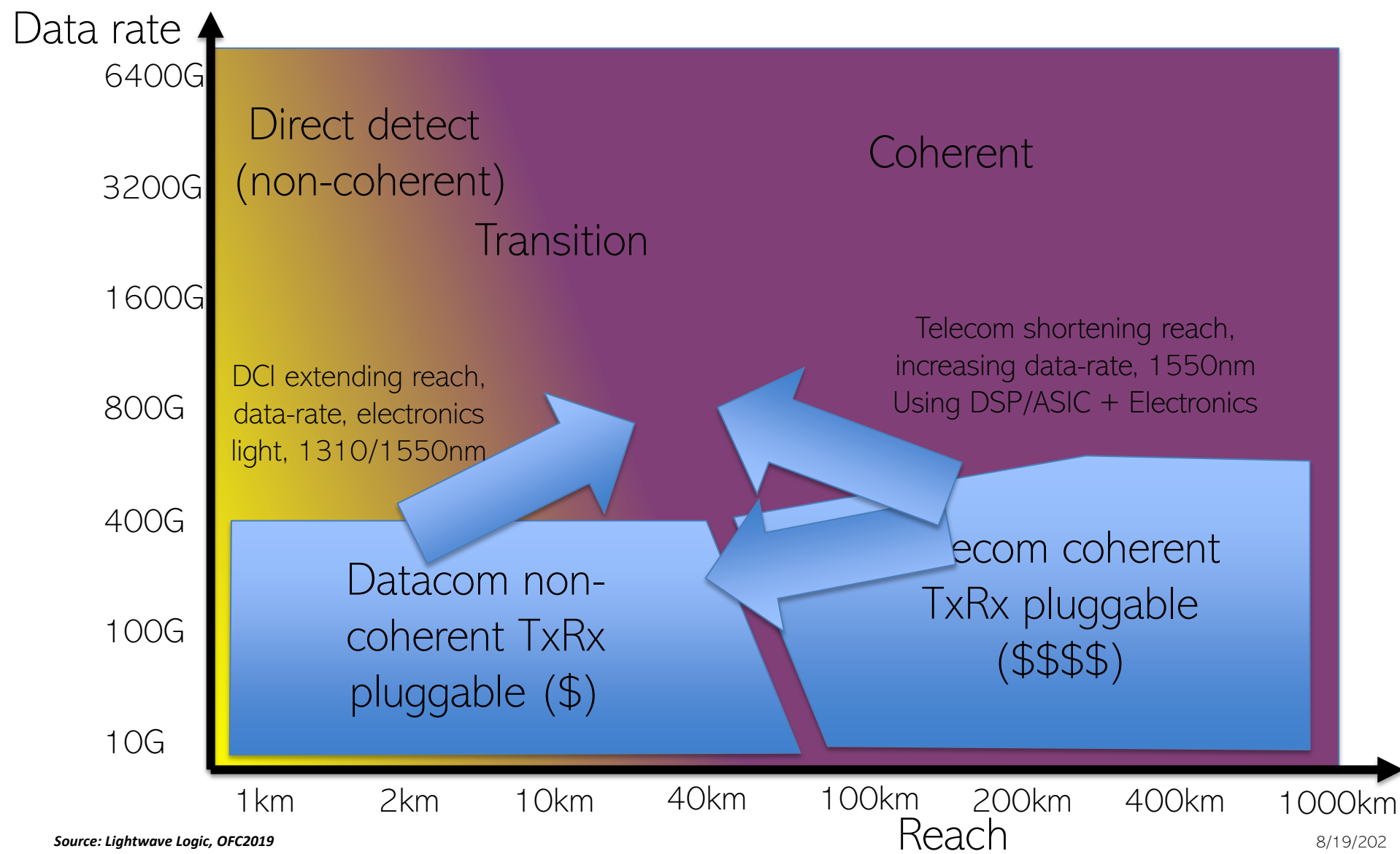


Direct detect vs coherent



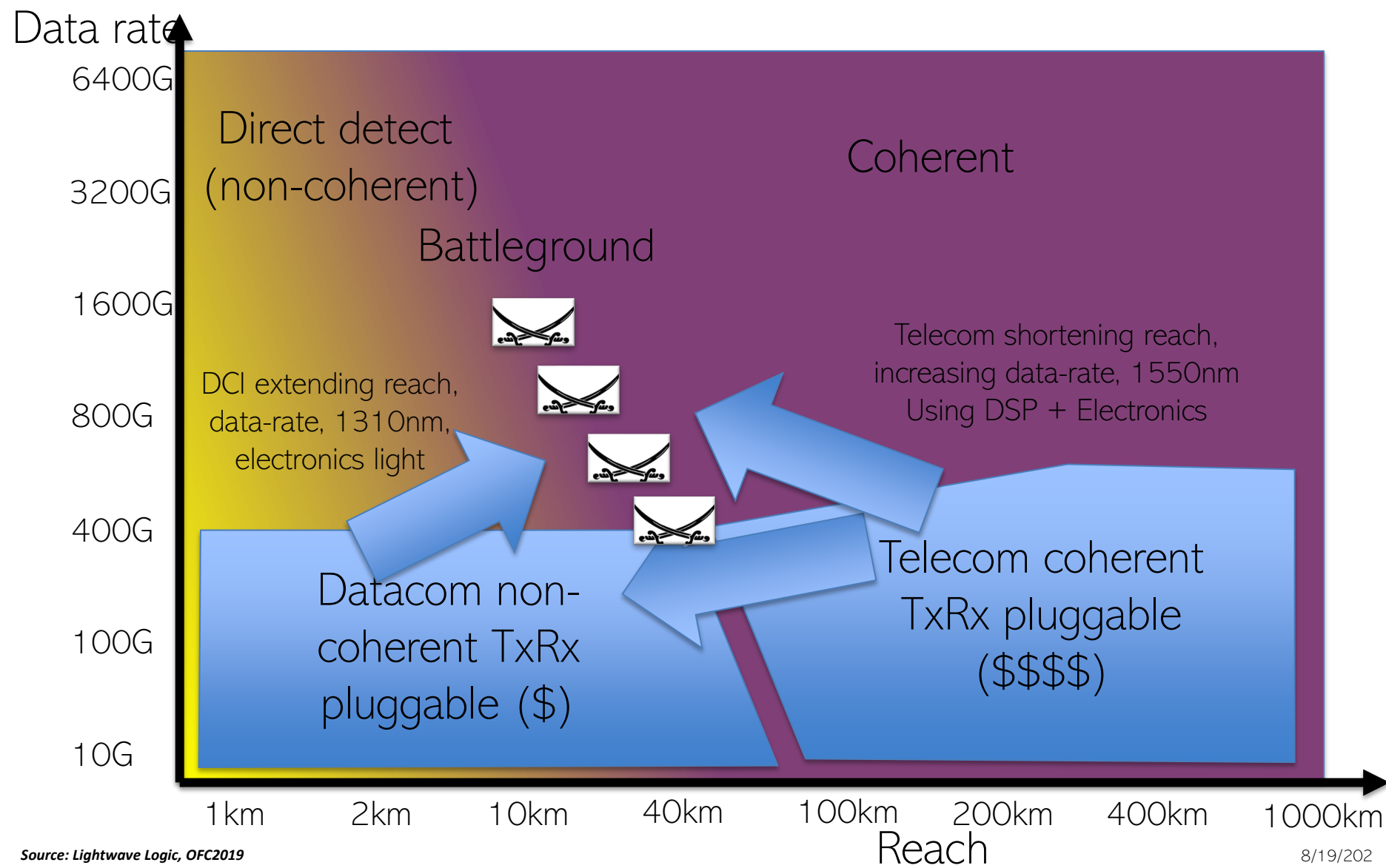


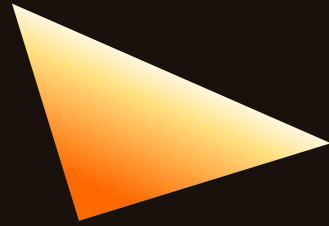
Merging fronts...cost, power and...





Battleground for cost, power, and speed





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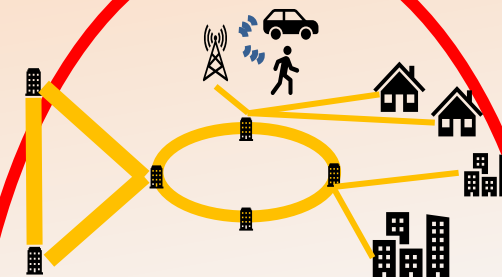
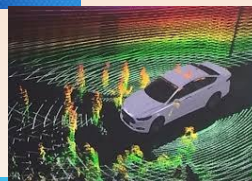
Robust...



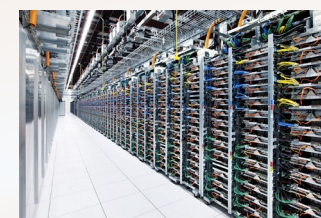


PIC opportunities expand but need robustness

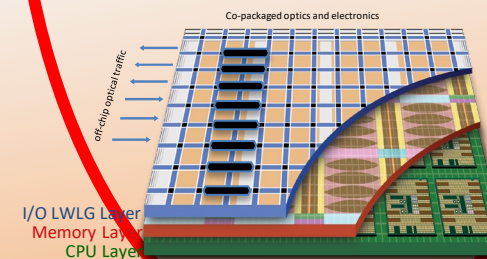
- 5G systems
- RF over fiber
- Automotive (LIDAR)
- Optical sensing
- Bio-photonic sensing
- Medical
- Instrumentation
- Others...



Telecommunications



Data communications



High performance computing

Maturity (and robustness) in Fiber Comm enables other markets

PLC semiconductor robustness/rel

- Telecommunications always relied on Telcordia testing (GR-468 etc)
 - 10-20 year lifetime, low FIT rates, accelerated testing
- Datacommunications (datacenters) looked at simplifying R&QA to reduce cost
 - Recent datacenter requirements proposed 3yr fork-lift equipment changes, and reduced R&QA expectations
 - Today's datacenter folks are now looking to re-establish high reliability testing to reduce failure rates from 1000s of photonics equipment
- Net net → R&QA is still critical and needs to be taken very seriously
 - Next generation PLCs must aim towards Telcordia requirements

R&QA needs to be aimed between datacom and telecom today

Electro-optic polymers meet the grade

- Standard Telcordia CR-468 reliability testing
- Robust materials

Test Item	Test Description	Specification: Method or Conditions	Sample Data	Passed Y/N
HTOL	High temperature operation life time test	Telcordia GR_468_COREi02 3.3.3.1; 2000 hrs at power, driver, bias and Ta = 85°C	11	Y
Low Temperature Storage	Storage only in low temperature	Telcordia GR_468_COREi02 3.3.2.1 -40°C, 72 Hour	11	Y
Mechanical Shock	Apply mechanical shocks to device	Telcordia GR_468_COREi02 3.3.1.1; mil-std-883 Method 2002.3	7	Y
Vibration	Apply vibration to devices	GR_468_COREi02 3.3.1.1; mil-std-883 Method 2007.2.	6	Y
Thermal Shock	Sudden exposure to extreme changes in temperature	Telcordia GR_468_COREi02 3.3.1.2; mil-std-883 Method 1011.9.	11	Y
Fiber Twist	Twist fiber pigtail	Telcordia GR_468_COREi02 3.3.1.3.1; FOTP 36.	8	Y
Fiber Side Pull	Pull fiber pigtail	Telcordia GR_468_COREi02 3.3.1.3.2; GR-326-CORE 4.4.3.5.	8	Y
Cable Retention	Apply force to the cable	Telcordia GR_468_COREi02 3.3.1.3.3; FOTP 6.	11	Y

Source: Lightwave Logic (LWLG), BrPhotonics

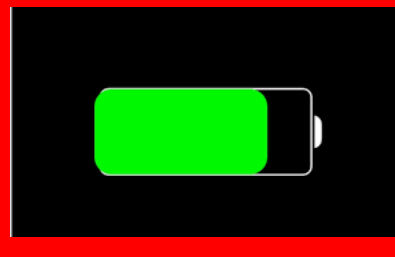
Battery of testing completed

We must deliver radical innovation

Faster devices
(100GHz+)



Lower Power
(Low voltage)



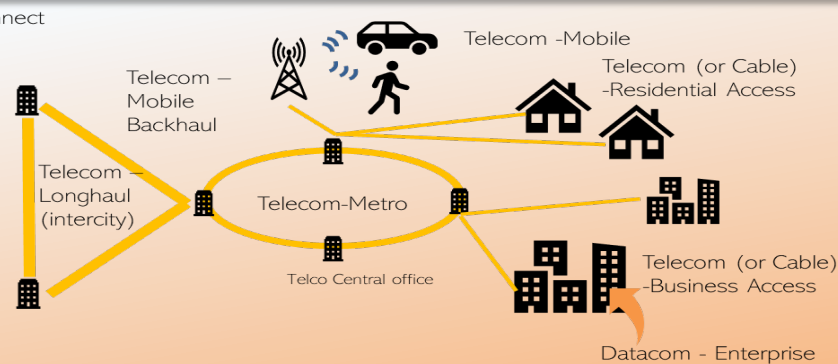
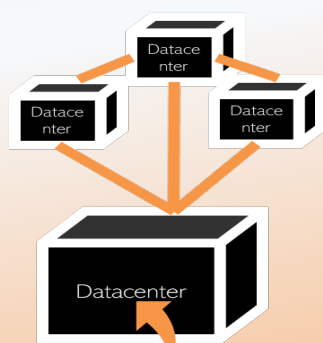
Lower cost
(Easy fab)



Robust
(Stable)



Datacom – Data Center Interconnect

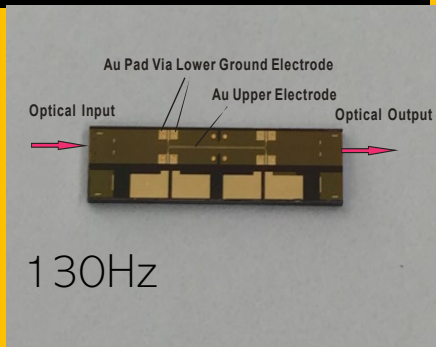


To enable faster, lower power, lower cost internet...

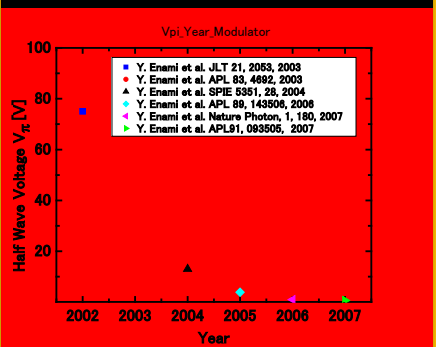


Electro-optic polymer example

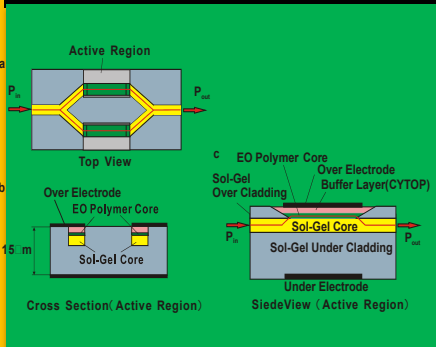
Faster devices
(100GHz+)



Lower Power
(Low voltage)



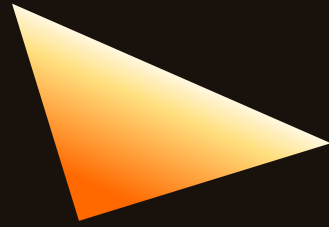
Low cost
(Easy fab)



Robust
(Stable)

Test Item	Test Description	Specification: Method or Conditions	Sample Data	Passed Y/N
HTOL	High temperature operation life time test	Telcordia GR-468_CORE02 3.3.2.1; 2000 hrs at power, driver, bias and Ts = 85°C	11	Y
Low Temperature Storage	Storage only in low temperature	Telcordia GR-468_CORE02 3.3.2.1; -40°C, 72 Hour	11	Y
Mechanical Shock	Apply mechanical shocks to device	Telcordia GR-468_CORE02 3.3.1.1; mil-std-883 Method 2002.3	7	Y
Vibration	Apply vibration to device	GR-468_CORE02 3.3.1.1; mil-std-883 Method 2007.2	6	Y
Thermal Shock	Sudden exposure to extreme changes in temperature	Telcordia GR-468_CORE02 3.3.1.2; mil-std-883 Method 1011.9	11	Y
Fiber Twist	Twist fiber pigtail	Telcordia GR-468_CORE02 3.3.1.3.1; FOTP-34	8	Y
Fiber Side Pull	Pull fiber pigtail	Telcordia GR-468_CORE02 3.3.1.3.2; GR-326-CORE 4.4.3.3	8	Y
Cable Retention	Apply force to the cable	Telcordia GR-468_CORE02 3.3.1.3.3; FOTP-6	11	Y

They enable *radical innovation...*



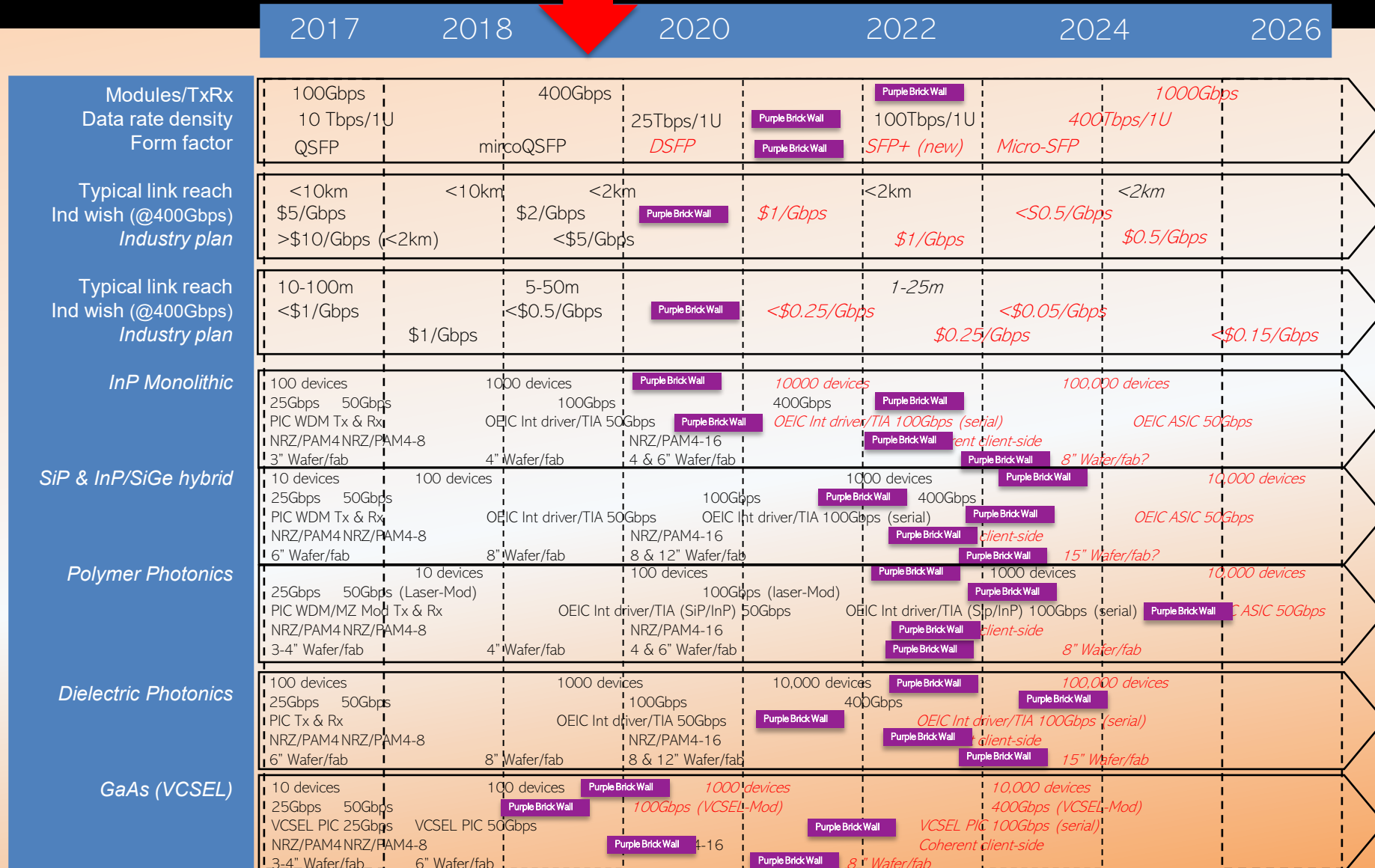
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OTCQB: LWLG

Roadmap update

Roadmaps: What did we predict in 2016?

Purple Brick Wall = Technology cost barrier



Slanted Red Font: Major industry efforts are required for commercialization
Source: Lightwave Logic

Actually pretty good → TxRx 400Gbps, <\$5/Gbps, 50Gbps+ devices



Purple Brick Wall = Technology cost barrier

	2017	2018	2020	2022	2024	2026
Modules/TxRx	100Gbps	400Gbps	25Tbps/1U	Purple Brick Wall	100Tbps/1U	1000Gbps
Data rate density	10 Tbps/1U	microQSFP	DSFP	Purple Brick Wall	SFP+ (new)	400Tbps/1U
Form factor	QSFP			Purple Brick Wall	Micro-SFP	
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$5/Gbps	\$2/Gbps	Purple Brick Wall	\$1/Gbps	<\$0.5/Gbps	<\$0.5/Gbps
Industry plan	>\$10/Gbps (<2km)	<\$5/Gbps		\$1/Gbps		\$0.5/Gbps
Typical link reach	10-100m	5-50m	Purple Brick Wall	1-25m		
Ind wish (@400Gbps)	<\$1/Gbps	<\$0.5/Gbps		<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
Industry plan	\$1/Gbps			\$0.25/Gbps		
InP Monolithic	100 devices	1000 devices	Purple Brick Wall	10000 devices	100,000 devices	
	25Gbps 50Gbps	100Gbps	Purple Brick Wall	400Gbps	Purple Brick Wall	
	PIC WDM Tx & Rx	OEIC Int driver/TIA 50Gbps	Purple Brick Wall	OEIC Int driver/TIA 100Gbps (serial)	OEIC ASIC 50Gbps	
	NRZ/PAM4 NRZ/PAM4-8		NRZ/PAM4-16	client-side		
	3" Wafer/fab	4" Wafer/fab	4 & 6" Wafer/fab	Purple Brick Wall	8" Wafer/fab?	
SiP & InP/SiGe hybrid	10 devices	100 devices		1000 devices	Purple Brick Wall	10,000 devices
	25Gbps 50Gbps		100Gbps	400Gbps	Purple Brick Wall	
	PIC WDM Tx & Rx	OEIC Int driver/TIA 50Gbps	OEIC Int driver/TIA 100Gbps (serial)	Purple Brick Wall	OEIC ASIC 50Gbps	
	NRZ/PAM4 NRZ/PAM4-8		NRZ/PAM4-16	client-side		
	6" Wafer/fab	8" Wafer/fab	8 & 12" Wafer/fab	Purple Brick Wall	15" Wafer/fab?	
Polymer Photonics	10 devices	100 devices		1000 devices	Purple Brick Wall	10,000 devices
	25Gbps 50Gbps (Laser-Mod)		100Gbps (Laser-Mod)		Purple Brick Wall	
	PIC WDM/MZ Mod Tx & Rx	OEIC Int driver/TIA (SiP/InP) 50Gbps	OEIC Int driver/TIA (SiP/InP) 100Gbps (serial)	Purple Brick Wall	OEIC ASIC 50Gbps	
	NRZ/PAM4 NRZ/PAM4-8		NRZ/PAM4-16	client-side		
	3-4" Wafer/fab	4" Wafer/fab	4 & 6" Wafer/fab	Purple Brick Wall	8" Wafer/fab	
Dielectric Photonics	100 devices	1000 devices	10,000 devices	Purple Brick Wall	100,000 devices	
	25Gbps 50Gbps	100Gbps	400Gbps	Purple Brick Wall	Purple Brick Wall	
	PIC Tx & Rx	OEIC Int driver/TIA 50Gbps	Purple Brick Wall	OEIC Int driver/TIA 100Gbps (serial)		
	NRZ/PAM4 NRZ/PAM4-8		NRZ/PAM4-16	client-side		
	6" Wafer/fab	8" Wafer/fab	8 & 12" Wafer/fab	Purple Brick Wall	15" Wafer/fab	
GaAs (VCSEL)	10 devices	100 devices	1000 devices		10,000 devices	
	25Gbps 50Gbps	Purple Brick Wall	100Gbps (VCSEL-Mod)	Purple Brick Wall	400Gbps (VCSEL-Mod)	
	VCSEL PIC 25Gbps	VCSEL PIC 50Gbps		Purple Brick Wall	VCSEL PIC 100Gbps (serial)	
	NRZ/PAM4 NRZ/PAM4-8		NRZ/PAM4-16	Coherent client-side		
	3-4" Wafer/fab	6" Wafer/fab		8" Wafer/fab		

Slanted Red Font: Major industry efforts are required for commercialization
Source: Lightwave Logic

New draft in 2019 → Where are we going?

Purple Brick Wall = Technology cost barrier

	2019	2020	2022	2024	2026	2028
Modules/TxRx	400Gbps	800Gbps	1600Gbps	3200Gbps		
Data rate density	25 Tbps/1U		100Tbps/1U	400Tbps/1U	1600Tbps/1U	
Form factor	Q/OSFP	OSFP/OBO/CP	OBO/CP	Co-Pkg/CoB	Micro-Co-Pkg/CoB	
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$2/Gbps	\$1/Gbps	\$0.5/Gbps	\$0.5/Gbps	<\$0.2/Gbps	\$0.2/Gbps
Industry plan	>\$5/Gbps (<2km)	<\$2/Gbps				
Typical link reach	10-100m	5-50m		1-25m		
Ind wish (@400Gbps)	<\$1/Gbps	<\$0.5/Gbps		<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
Industry plan	\$1/Gbps			\$0.25/Gbps		
InP Monolithic	100 devices	1000 devices	10000 devices	100,000 devices		
	25GHz 50GHz	70GHz	90GHz	100GHz		
	PIC WDM Tx & Rx (30GHz)	OEIC Int driver/TIA 50Gbps (50GHz)	OEIC Int driver/TIA 100Gbps (70GHz)	OEIC ASIC 50Gbps (50GHz)		
	NRZ/PAM4 NRZ/PAM4-8	NRZ/PAM4-16	Coherent client-side	Coherent DSP-less		
	3" Wafer/fab	4" Wafer/fab	4 & 6" Wafer/fab	8" Wafer/fab?		
SiP & InP/SiGe hybrid	10 devices	100 devices	1000 devices	10,000 devices		
	25GHz 50GHz	70GHz	70GHz (400Gbps)	70GHz (400Gbps)		
	PIC WDM Tx & Rx (30GHz)	OEIC Int driver/TIA 50Gbps (50GHz)	OEIC Int driver/TIA 100Gbps (serial)	OEIC Int driver/TIA 100Gbps (serial)		
	NRZ/PAM4 NRZ/PAM4-8	NRZ/PAM4-16	Coherent client-side	Coherent DSP-less		
	6" Wafer/fab	8" Wafer/fab	8 & 12" Wafer/fab	15" Wafer/fab?		
Polymer Photonics	10 devices	100 devices	1000 devices	10,000 devices		
	25GHz 50GHz (Laser-Mod)	70GHz (laser-Mod)	100GHz (150Gbps serial)	100GHz (150Gbps serial)		
	PIC WDM/MZ Mod Tx & Rx	OEIC Int driver/TIA (SiP/InP) 50GHz	OEIC Int driver/TIA (SiP/InP) 70GHz (s)	OEIC ASIC 70GHz		
	NRZ/PAM4 NRZ/PAM4-8	NRZ/PAM4-16	Coherent client-side	Coherent client-side		
	3-4" Wafer/fab	4" Wafer/fab	4 & 6" Wafer/fab	8" Wafer/fab		
Dielectric Photonics	100 devices	1000 devices	10,000 devices	100,000 devices		
	25GHz 50GHz	70GHz	70GHz (400Gbps)	70GHz (400Gbps)		
	PIC Tx & Rx	OEIC Int driver/TIA 50GHz	OEIC Int driver/TIA 70GHz	OEIC Int driver/TIA 70GHz		
	NRZ/PAM4 NRZ/PAM4-8	NRZ/PAM4-16	Coherent client-side	Coherent client-side		
	6" Wafer/fab	8" Wafer/fab	8 & 12" Wafer/fab	15" Wafer/fab		
GaAs (VCSEL)	100 devices	1000 devices	10,000 devices	100,000 devices		
	25GHz 50GHz	70GHz	70GHz (VCSEL-Mod)	70GHz (VCSEL-Mod)		
	VCSEL PIC 25GHz	VCSEL PIC 50GHz	VCSEL PIC 70GHz (100Gbps)	VCSEL PIC 70GHz (100Gbps)		
	NRZ/PAM4 NRZ/PAM4-8	NRZ/PAM4-16	Coherent client-side	Coherent client-side		
	6" Wafer/fab	8" Wafer/fab	8" Wafer/fab	8" Wafer/fab		

Slanted Red Font: Major industry efforts are required for commercialization

Source: Lightwave Logic

800 and 1 600Gbps; very high bandwidth 70GHz, co-packaging, low power, hybrid integration, low \$/Gbps



	2019	2020	2022	2024	2026	2028
Modules/TxRx	400Gbps	800Gbps	1600Gbps	3200Gbps		
Data rate density	25 Tbps/1U		100Tbps/1U	400Tbps/1U	1600Tbps/1U	
Form factor	Q/OSFP	OSFP/OBO/CP	OBO/CP	Co-Pkg/CoB	Micro-Co-Pkg/CoB	
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$2/Gbps	\$1/Gbps	\$0.5/Gbps	\$0.5/Gbps	<\$0.2/Gbps	\$0.2/Gbps
Industry plan	>\$5/Gbps (<2km)	<\$2/Gbps				
Typical link reach	10-100m	5-50m	1-25m			
Ind wish (@400Gbps)	<\$1/Gbps	<\$0.5/Gbps	<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps	
Industry plan	\$1/Gbps					
InP Monolithic	100 devices 25GHz 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 NRZ/PAM4-8 3" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4" Wafer/fab	Purple Brick Wall 10000 devices 90GHz OEIC Int driver/TIA 100Gbps (70GHz) Coherent client-side 4 & 6" Wafer/fab	Purple Brick Wall 10000 devices 100GHz OEIC Int driver/TIA 100Gbps (70GHz) Coherent client-side 8" Wafer/fab?	100,000 devices OEIC ASIC 50Gbps (50GHz)	
SiP & InP/SiGe hybrid	10 devices 25GHz 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	100 devices 70GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 8" Wafer/fab	1000 devices 70GHz (100Gbps) OEIC Int driver/TIA 50Gbps (50GHz) Coherent client-side 8 & 12" Wafer/fab	Purple Brick Wall 10,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 100Gbps (serial) Coherent DSP-less 8" Wafer/fab	Purple Brick Wall 15" Wafer/fab?	
Polymer Photonics	10 devices 25GHz 50GHz (Laser-Mod) PIC WDM/MZ Mod Tx & Rx NRZ/PAM4 NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz (laser-Mod) OEIC Int driver/TIA (SiP/InP) 50GHz NRZ/PAM4-16 4" Wafer/fab	10000 devices 100GHz (150Gbps serial) OEIC Int driver/TIA (SiP/InP) 70GHz (s Coherent client-side 8" Wafer/fab	Purple Brick Wall 10000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz (s Coherent client-side 15" Wafer/fab	Purple Brick Wall OEIC ASIC 70GHz	
Dielectric Photonics	100 devices 25GHz 50GHz PIC Tx & Rx NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50GHz NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz OEIC Int driver/TIA 50GHz NRZ/PAM4-16 8 & 12" Wafer/fab	Purple Brick Wall 100,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz Coherent client-side 15" Wafer/fab		
GaAs (VCSEL)	100 devices 25GHz 50GHz VCSEL PIC 25GHz NRZ/PAM4 NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz VCSEL PIC 50GHz NRZ/PAM4-16 8" Wafer/fab	10000 devices 70GHz VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab	Purple Brick Wall 100,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 70GHz Coherent client-side 15" Wafer/fab		

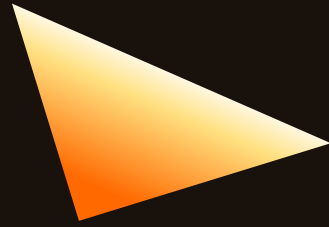
Slanted Red Font: Major industry efforts are required for commercialization
Source: Lightwave Logic

Call to action...



- Roadmap slides convey clear messages
 - Challenges to move data faster, more efficiently are not slowing down
 - PIC platforms are critical for size, weight, and power
 - Innovation is desperately needed amongst our current technological platforms
- How are we going to make this happen?
 - We support the roadmaps and use roadmaps to generate investment (foundries, clusters, centers etc)

Learn to shout at the political level for photonics...

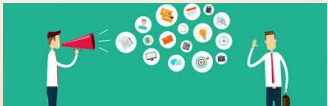


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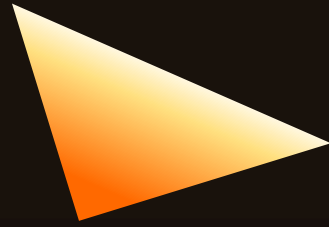
OTCQB: LWLG

Summary

Summary

- Internet still growing quickly driven by video
 - Internet key application, others emerging (bio, automotive, medical...) ✓
 - Strong \$B markets in fiber communications with forecasted growth
- Integrated photonics continue to be strong ✓
 - PICs will mature over the decade in fiber communications
 - Trend to co-packaging, low power, high bandwidth, low cost coherent
 - Hybrid PICs will become common-place to increase specifications
- We see our polymers solving customer headaches ✓
 - Our polymers add speed dimension, low power, cost effective to internet
- Call to action? 
 - Utilize our roadmaps to energize political levels internationally ✓
 - Let's make the roadmaps our tool for success...

Let's make the next decade a photonic one...*radical innovation*



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OTCQB: LWLG

Thank you
Symbol OTCQB: LWLG